有关敝公司产品的注意事项

【一般电子设备(一般环境)】

请务必在使用敝司产品之前阅读。

⚠ 注 意

- 本产品目录中所记载的内容为2017年10月之内容。因改良等原因，可能会不经预告而变更记载内容，所以请务必在使用前先确认最新的产品信息。未按照本产品目录中所记载的内容或交货规格说明书使用敝公司产品的，即便其致使使用设备发生损害、瑕疵等时，敝公司也不承担任何责任，敬请悉知。

- 就规格相关的详细内容，敝公司备有交货规格说明书，详情请向敝公司咨询。

- 使用敝公司产品时，请务必事先安装到设备之后，在实际使用的环境下进行评估和确认。

- 本产品目录中所记载的产品可使用于一般电子设备 [音像设备、办公自动化设备、家电产品、办公设备、信息/通讯设备 (手机、电脑等)] 以及医疗设备 (国际 (IMDRF) 第一类，第二类) 。因此，若考虑将本产品目录中所记载的产品使用于可能会直接危及生命或身体的设备 [运输用设备 (汽车驱动控制设备、火车控制设备、船舶控制设备等) 、交通信号设备、防灾设备、医疗设备 (国际 (IMDRF) 第三类) 、高公共性信息通信设备 (电话交换机以及电话、无线、广播电视等基站)] 等时，请务必事先向敝公司咨询。

  另外，请勿将敝公司产品使用于对安全性和可靠性要求较高的设备 (航天设备、航空设备※、医疗设备 (国际 (IMDRF) 第四类) 、原子能控制设备、海底设备、军事设备等) 。

  ※ 注释 ： 仅限于对航空设备的安全运行不产生直接干扰的设备[机内娱乐设备、机内照明设备、电动座椅、餐饮设备等]，在满足敝公司另行指定的相关条件时，亦可将敝公司产品用于以上用途。在贵公司考虑将敝公司的产品用于以上用途时，请务必事先向敝公司咨询相关的信息。

  且即便属于一般电子设备，使用于对安全性和可靠性要求较高的设备、电路上时，敝公司建议进行充分的安全评估，并根据需要，在设计时追加保护电路等。

  未经敝公司的事先书面同意，把本产品目录中所记载的产品使用于前述需要向敝公司咨询的设备或敝公司禁止使用的设备，从而给客户或第三方造成损害的，敝公司不承担任何责任，敬请悉知。

- 本产品目录中所记载的信息是用于说明相关产品的典型操作以及相关应用。此类信息的使用不代表对于敝公司以及第三方的知识产权以及其他权利的使用许可或是不侵权保证。

- 敝公司产品的保证范围仅限于交付的敝公司产品单品，就敝公司产品的故障或瑕疵所誘発的损害，敝公司不承担任何责任，敬请悉知。但是，以书面形式另行签署了交易基本合同书，品质保证协定书等时，敝公司将根据该合同等的条件提供保证。

- 本产品目录中所记载的内容适用于从敝公司营业所、销售子公司、销售代理店 (即“正规销售渠道”) 购买的敝公司产品，并不适用于从上述以外的渠道购买的敝公司产品，敬请悉知。

- 出口相关注意事项

  本产品目录中所记载的部分产品在出口时须事先确认《外汇和对外贸易法》以及美国出口管理的相关法规，并办理相关手续。如有不明之处，请向敝公司咨询。

多层共模模式扼流线圈(MC 系列F 型)

回流焊

■型号标示法　　※使用温度范围: -40～+85℃

M	C	F	0	8	0	6	2	G	1	2	0	—	T	△
①			②				③	④	⑤			⑥		⑦

△＝空格

①类型

代码	类型
MCF	多层共模模式扼流线圈

②尺寸

代码	尺寸 [mm]
0605	0.65×0.50
0806	0.85×0.65
1210	1.25×1.0
2010	2.0×1.0

③匝数

代码	匝数
2	2 线
4	4 线

④材料

代码	材料
G	材料不同时，阻抗值也有所变化
E	
H	

⑤标称共模阻抗值

代码 (例)	标称共模阻抗值〔Ω〕
120	12
900	90

⑥包装

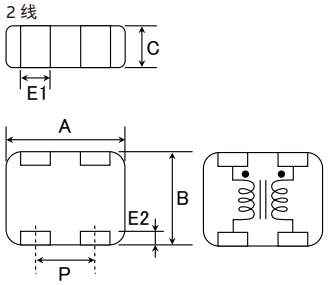
代码	包装
—T	卷盘带装

⑦本公司管理记号

代码	本公司管理记号
△	标准品

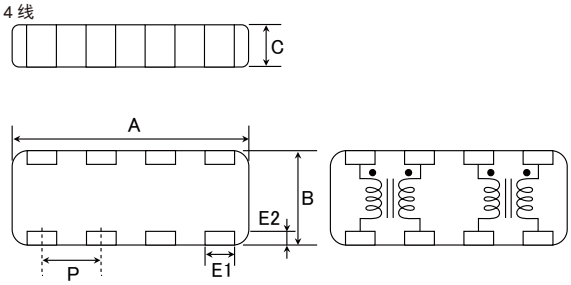
■标准外型尺寸 / 标准数量 / 等价电路

2 线



等价电路
・没有极性

4 线



等价电路
・没有极性

Type	A	B	C	E1	E2	P	标准数量 [pcs] 卷盘带装
MCF0605	0.65±0.05 (0.026±0.002)	0.50±0.05 (0.020±0.002)	0.30±0.05 (0.012±0.002)	0.15±0.1 (0.006±0.004)	0.12±0.1 (0.005±0.004)	0.40±0.10 (0.016±0.004)	15000
MCF0806	0.85±0.05 (0.033±0.002)	0.65±0.05 (0.026±0.002)	0.40±0.05 (0.016±0.002)	0.27±0.1 (0.011±0.004)	0.2 +0.05/−0.1 (0.008 +0.002/−0.004)	0.50±0.10 (0.020±0.004)	10000
MCF1210	1.0±0.15 (0.039±0.006)	1.25±0.15 (0.049±0.006)	0.55±0.1 (0.022±0.004)	0.3±0.1 (0.012±0.004)	0.2±0.1 (0.008±0.004)	0.55±0.10 (0.022±0.004)	5000
MCF2010	2.0±0.15 (0.079±0.006)	1.0±0.15 (0.039±0.006)	0.45±0.1 (0.018±0.004)	0.25 +0.15/−0.1 (0.010 +0.006/−0.004)	0.25±0.15 (0.010±0.006)	0.50±0.10 (0.020±0.004)	4000

单位: mm (inch)

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另外，有关各产品的详细信息(特性图、可靠性信息、使用时的注意事项等)，请参阅弊司网站(http://www.ty-top.com/)。

■型号一览

●MCF0605型

型号	EHS	匝数	共模阻抗 [Ω]	测试频率 [MHz]	直流电阻 [Ω] (max.)	额定电流 [A] (max.)	额定电压 [V]	绝缘阻抗 [MΩ] (min.)
MCF0605 2G120-T	RoHS	2	12±5	100	2.5	0.05	5	100
MCF0605 2G350-T	RoHS	2	35±20%	100	5.0	0.05	5	100
MCF0605 2E600-T	RoHS	2	60±25%	100	3.5	0.05	5	100
MCF0605 2E900-T	RoHS	2	90±20%	100	3.9	0.05	5	100

●MCF0806型

型号	EHS	匝数	共模阻抗 [Ω]	测试频率 [MHz]	直流电阻 [Ω] (max.)	额定电流 [A] (max.)	额定电压 [V]	绝缘阻抗 [MΩ] (min.)
MCF0806 2G120-T	RoHS	2	12±5	100	2.5	0.13	5	100
MCF0806 2G470-T	RoHS	2	47±20%	100	4.0	0.10	5	100
MCF0806 2G900-T	RoHS	2	90±20%	100	5.0	0.10	5	100
MCF0806 2E300-T	RoHS	2	30±25%	100	1.5	0.15	5	100

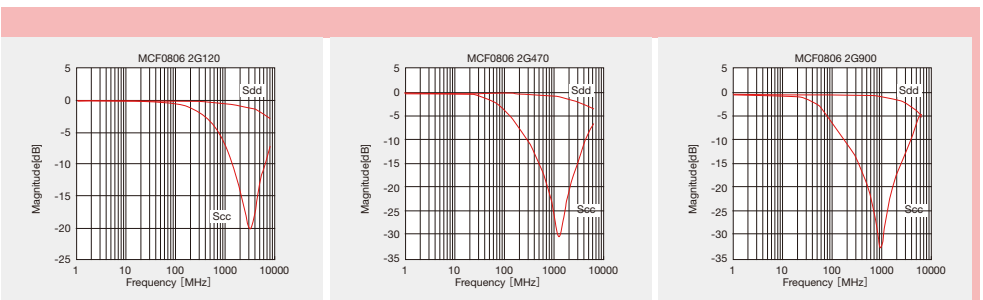
●MCF1210型

型号	EHS	匝数	共模阻抗 [Ω]	测试频率 [MHz]	直流电阻 [Ω] (max.)	额定电流 [A] (max.)	额定电压 [V]	绝缘阻抗 [MΩ] (min.)
MCF1210 2G400-T	RoHS	2	40±25%	100	2.5	0.10	5	100
MCF1210 2G900-T	RoHS	2	90±25%	100	4.5	0.10	5	100
MCF1210 2H500-T	RoHS	2	50±25%	100	1.5	0.16	5	100
MCF1210 2H900-T	RoHS	2	90±20%	100	2.5	0.15	5	100

●MCF2010型

型号	EHS	匝数	共模阻抗 [Ω]	测试频率 [MHz]	直流电阻 [Ω] (max.)	额定电流 [A] (max.)	额定电压 [V]	绝缘阻抗 [MΩ] (min.)
MCF2010 4G900-T	RoHS	4	90±25%	100	4.5	0.10	5	100

■特性图



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Multilayer chip inductors
Multilayer chip inductors for high frequency, Multilayer chip bead inductors
Multilayer common mode choke coils (MC series F type)
Metal Multilayer Chip Power Inductors (MCOIL™ MC series)

■PACKAGING

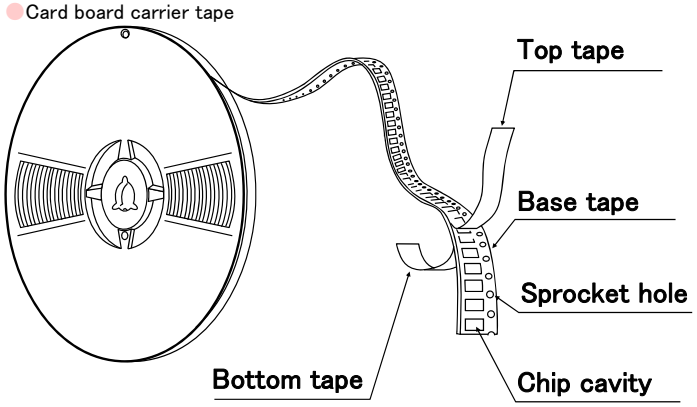
①Minimum Quantity

●Tape & Reel Packaging

Type	Thickness mm (inch)	Standard Quantity [pcs]	
		Paper Tape	Embossed Tape
CK1608 (0603)	0.8 (0.031)	4000	—
CK2125 (0805)	0.85 (0.033)	4000	—
	1.25 (0.049)	—	2000
CKS2125 (0805)	0.85 (0.033)	4000	—
	1.25 (0.049)	—	2000
CKP1608 (0603)	0.8 (0.031)	4000	—
CKP2012 (0805)	0.9 (0.035)	—	3000
CKP2016 (0806)	0.9 (0.035)	—	3000
CKP2520 (1008)	0.7 (0.028)	—	3000
	0.9 (0.035)	—	3000
	1.1 (0.043)	—	2000
NM2012 (0805)	0.9 (0.035)	—	3000
NM2520 (1008)	0.9 (0.035)	—	3000
	1.1 (0.043)	—	2000
LK1005 (0402)	0.5 (0.020)	10000	—
LK1608 (0603)	0.8 (0.031)	4000	—
LK2125 (0805)	0.85 (0.033)	4000	—
	1.25 (0.049)	—	2000
HK0603 (0201)	0.3 (0.012)	15000	—
HK1005 (0402)	0.5 (0.020)	10000	—
HK1608 (0603)	0.8 (0.031)	4000	—
HK2125 (0805)	0.85 (0.033)	—	4000
	1.0 (0.039)	—	3000
HKQ0402 (01005)	0.2 (0.008)	20000	40000
HKQ0603W (0201)	0.3 (0.012)	15000	—
HKQ0603S (0201)	0.3 (0.012)	15000	—
HKQ0603U (0201)	0.3 (0.012)	15000	—
AQ105 (0402)	0.5 (0.020)	10000	—
BK0402 (01005)	0.2 (0.008)	20000	—
BK0603 (0201)	0.3 (0.012)	15000	—
BK1005 (0402)	0.5 (0.020)	10000	—
BKH0603 (0201)	0.3 (0.012)	15000	—
BKH1005 (0402)	0.5 (0.020)	10000	—
BK1608 (0603)	0.8 (0.031)	4000	—
BK2125 (0805)	0.85 (0.033)	4000	—
	1.25 (0.049)	—	2000
BK2010 (0804)	0.45 (0.018)	4000	—
BK3216 (1206)	0.8 (0.031)	—	4000
BKP0402 (01005)	0.2 (0.008)	20000	—
BKP0603 (0201)	0.3 (0.012)	15000	—
BKP1005 (0402)	0.5 (0.020)	10000	—
BKP1608 (0603)	0.8 (0.031)	4000	—
BKP2125 (0805)	0.85 (0.033)	4000	—
MCF0605 (0202)	0.3 (0.012)	15000	—
MCF0806 (0302)	0.4 (0.016)	—	10000
MCF1210 (0504)	0.55 (0.022)	—	5000
MCF2010 (0804)	0.45 (0.018)	—	4000
MCFK1608 (0603)	0.6 (0.024)	4000	—
MCFE1608 (0603)	0.65 (0.026)	4000	—
MCKK1608 (0603)	1.0 (0.039)		3000
MCHK2012 (0806)	0.8 (0.031)	4000	—
MCKK2012 (0805)	1.0 (0.039)	–	3000

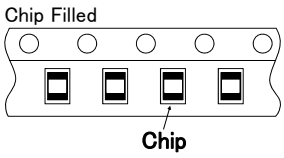
②Taping material

Card board carrier tape

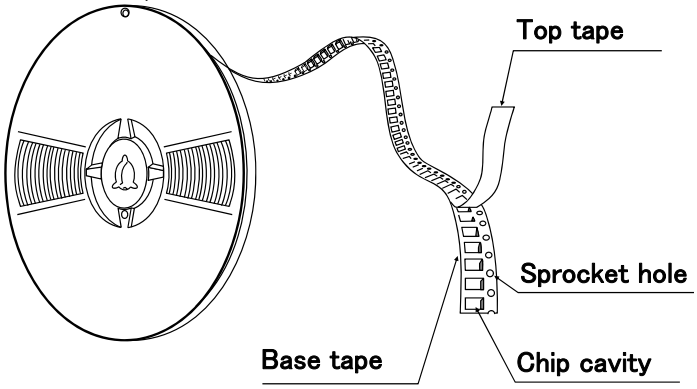


CK	1608
CKP	1608
CK	2125
CKS	2125
LK	1005
LK	1608
LK	2125
HK	0603
HK	1005
HK	1608
HKQ	0402
HKQ	0603
AQ	105

BK	0402
BK	0603
BK	1005
BK	1608
BK	2125
BK	2010
BKP	0402
BKP	0603
BKP	1005
BKP	1608
BKP	2125
BKH	0603
BKH	1005
MCF	0605
MC	1608
MC	2012

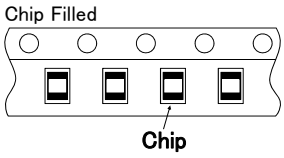


Embossed Tape



CK	2125
CKS	2125
CKP	2012
CKP	2016
CKP	2520
NM	2012
NM	2520
LK	2125
HKQ	0402
HK	2125

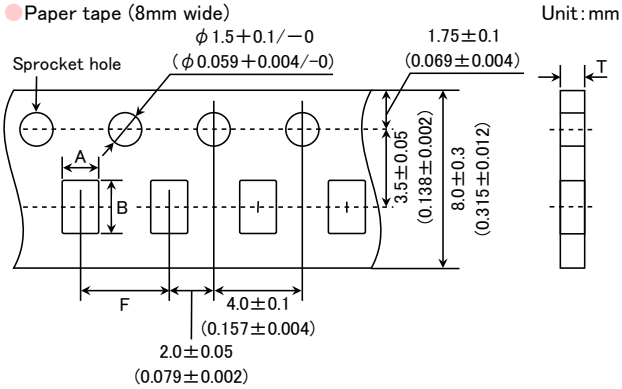
BK	2125
BK	3216
MCF	0806
MCF	1210
MCF	2010
MC	1608
MC	2012



③Taping Dimensions

Paper tape (8mm wide)

Unit : mm (inch)

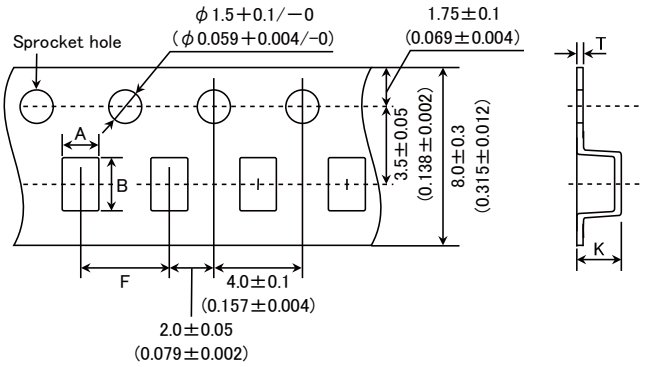


Type	Thickness mm(inch)	Chip cavity		Insertion Pitch	Tape Thickness
		A	B	F	T
CK1608(0603)	0.8 (0.031)	1.0±0.2 (0.039±0.008)	1.8±0.2 (0.071±0.008)	4.0±0.1 (0.157±0.004)	1.1max (0.043max)
CK2125(0805)	0.85(0.033)	1.5±0.2 (0.059±0.008)	2.3±0.2 (0.091±0.008)	4.0±0.1 (0.157±0.004)	1.1max (0.043max)
CKS2125(0805)	0.85(0.033)	1.5±0.2 (0.059±0.008)	2.3±0.2 (0.091±0.008)	4.0±0.1 (0.157±0.004)	1.1max (0.043max)
CKP1608(0603)	0.8 (0.031)	1.0±0.2 (0.039±0.008)	1.8±0.2 (0.071±0.008)	4.0±0.1 (0.157±0.004)	1.1max (0.043max)
LK1005(0402)	0.5 (0.020)	0.65±0.1 (0.026±0.004)	1.15±0.1 (0.045±0.004)	2.0±0.05 (0.079±0.002)	0.8max (0.031max)
LK1608(0603)	0.8 (0.031)	1.0±0.2 (0.039±0.008)	1.8±0.2 (0.071±0.008)	4.0±0.1 (0.157±0.004)	1.1max (0.043max)
LK2125(0805)	0.85(0.033)	1.5±0.2 (0.059±0.008)	2.3±0.2 (0.091±0.008)	4.0±0.1 (0.157±0.004)	1.1max (0.043max)
HK0603(0201)	0.3 (0.012)	0.40±0.06 (0.016±0.002)	0.70±0.06 (0.028±0.002)	2.0±0.05 (0.079±0.002)	0.45max (0.018max)
HK1005(0402)	0.5 (0.020)	0.65±0.1 (0.026±0.004)	1.15±0.1 (0.045±0.004)	2.0±0.05 (0.079±0.002)	0.8max (0.031max)
HK1608(0603)	0.8 (0.031)	1.0±0.2 (0.039±0.008)	1.8±0.2 (0.071±0.008)	4.0±0.1 (0.157±0.004)	1.1max (0.043max)
HKQ0402(01005)	0.2 (0.008)	0.25±0.04 (0.010±0.002)	0.45±0.04 (0.018±0.002)	2.0±0.05 (0.079±0.002)	0.36max (0.014max)
HKQ0603W(0201)	0.3 (0.012)	0.40±0.06 (0.016±0.002)	0.70±0.06 (0.028±0.002)	2.0±0.05 (0.079±0.002)	0.45max (0.018max)
HKQ0603S(0201)	0.3 (0.012)	0.40±0.06 (0.016±0.002)	0.70±0.06 (0.028±0.002)	2.0±0.05 (0.079±0.002)	0.45max (0.018max)
HKQ0603U(0201)	0.3 (0.012)	0.40±0.06 (0.016±0.002)	0.70±0.06 (0.028±0.002)	2.0±0.05 (0.079±0.002)	0.45max (0.018max)
AQ105(0402)	0.5 (0.020)	0.75±0.1 (0.030±0.004)	1.15±0.1 (0.045±0.004)	2.0±0.05 (0.079±0.002)	0.8max (0.031max)
BK0402(01005)	0.2 (0.008)	0.25±0.04 (0.010±0.002)	0.45±0.04 (0.018±0.002)	2.0±0.05 (0.079±0.002)	0.36max (0.014max)
BK0603(0201)	0.3 (0.012)	0.40±0.06 (0.016±0.002)	0.70±0.06 (0.028±0.002)	2.0±0.05 (0.079±0.002)	0.45max (0.018max)
BK1005(0402)	0.5 (0.020)	0.65±0.1 (0.026±0.004)	1.15±0.1 (0.045±0.004)	2.0±0.05 (0.079±0.002)	0.8max (0.031max)
BK1608(0603)	0.8 (0.031)	1.0±0.2 (0.039±0.008)	1.8±0.2 (0.071±0.008)	4.0±0.1 (0.157±0.004)	1.1max (0.043max)
BK2125(0805)	0.85(0.033)	1.5±0.2 (0.059±0.008)	2.3±0.2 (0.091±0.008)	4.0±0.1 (0.157±0.004)	1.1max (0.043max)
BK2010(0804)	0.45(0.018)	1.2±0.1 (0.047±0.004)	2.17±0.1 (0.085±0.004)	4.0±0.1 (0.157±0.004)	0.8max (0.031max)
BKP0402(01005)	0.2 (0.008)	0.25±0.04 (0.010±0.002)	0.45±0.04 (0.018±0.002)	2.0±0.05 (0.079±0.002)	0.36max (0.014max)
BKP0603(0201)	0.3 (0.012)	0.40±0.06 (0.016±0.002)	0.70±0.06 (0.028±0.002)	2.0±0.05 (0.079±0.002)	0.45max (0.018max)
BKP1005(0402)	0.5 (0.020)	0.65±0.1 (0.026±0.004)	1.15±0.1 (0.045±0.004)	2.0±0.05 (0.079±0.002)	0.8max (0.031max)
BKP1608(0603)	0.8 (0.031)	1.0±0.2 (0.039±0.008)	1.8±0.2 (0.071±0.008)	4.0±0.1 (0.157±0.004)	1.1max (0.043max)
BKP2125(0805)	0.85(0.033)	1.5±0.2 (0.059±0.008)	2.3±0.2 (0.091±0.008)	4.0±0.1 (0.157±0.004)	1.1max (0.043max)
BKH0603(0201)	0.3 (0.012)	0.40±0.06 (0.016±0.002)	0.70±0.06 (0.028±0.002)	2.0±0.05 (0.079±0.002)	0.45max (0.018max)
BKH1005(0402)	0.5 (0.020)	0.65±0.1 (0.026±0.004)	1.15±0.1 (0.045±0.004)	2.0±0.05 (0.079±0.002)	0.8max (0.031max)
MCF0605(0202)	0.3 (0.012)	0.62±0.03 (0.024±0.001)	0.77±0.03 (0.030±0.001)	2.0±0.05 (0.079±0.002)	0.45max (0.018max)
MCFK1608(0603)	0.6 (0.024)	1.1±0.05 (0.043±0.002)	1.9±0.05 (0.075±0.002)	4.0±0.1 (0.157±0.004)	0.72max (0.028max)
MCFE1608(0603)	0.65(0.026)	1.1±0.05 (0.043±0.002)	1.9±0.05 (0.075±0.002)	4.0±0.1 (0.157±0.004)	0.9max (0.035max)
MCHK2012(0805)	0.8 (0.031)	1.55±0.2 (0.061±0.008)	2.3±0.2 (0.091±0.008)	4.0±0.1 (0.157±0.004)	0.9max (0.035max)

Unit : mm(inch)

● Embossed Tape (8mm wide)

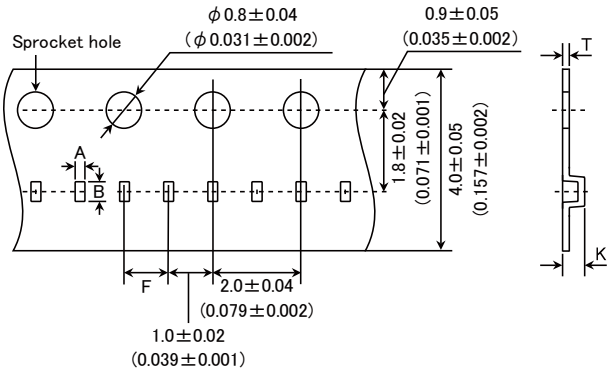
Unit : mm (inch)



Type	Thickness mm (inch)	Chip cavity		Insertion Pitch	Tape Thickness	
		A	B	F	K	T
CK2125 (0805)	1.25 (0.049)	1.5±0.2 (0.059±0.008)	2.3±0.2 (0.091±0.008)	4.0±0.1 (0.157±0.004)	2.0 (0.079)	0.3 (0.012)
CKS2125 (0805)	1.25 (0.049)	1.5±0.2 (0.059±0.008)	2.3±0.2 (0.091±0.008)	4.0±0.1 (0.157±0.004)	2.0 (0.079)	0.3 (0.012)
CKP2012 (0805)	0.9 (0.035)	1.55±0.2 (0.061±0.008)	2.3±0.2 (0.091±0.008)	4.0±0.1 (0.157±0.004)	1.3 (0.051)	0.3 (0.012)
CKP2016 (0806)	0.9 (0.035)	1.8±0.1 (0.071±0.004)	2.2±0.1 (0.087±0.004)	4.0±0.1 (0.157±0.004)	1.3 (0.051)	0.25 (0.01)
CKP2520 (1008)	0.7 (0.028)	2.3±0.1 (0.091±0.004)	2.8±0.1 (0.110±0.004)	4.0±0.1 (0.157±0.004)	1.4 (0.055)	0.3 (0.012)
	0.9 (0.035)				1.4 (0.055)	
	1.1 (0.043)				1.7 (0.067)	
NM2012 (0805)	0.9 (0.035)	1.55±0.2 (0.061±0.008)	2.3±0.2 (0.091±0.008)	4.0±0.1 (0.157±0.004)	1.3 (0.051)	0.3 (0.012)
NM2520 (1008)	0.9 (0.035)	2.3±0.1 (0.091±0.004)	2.8±0.1 (0.110±0.004)	4.0±0.1 (0.157±0.004)	1.4 (0.055)	0.3 (0.012)
	1.1 (0.043)				1.7 (0.067)	
LK2125 (0805)	1.25 (0.049)	1.5±0.2 (0.059±0.008)	2.3±0.2 (0.091±0.008)	4.0±0.1 (0.157±0.004)	2.0 (0.079)	0.3 (0.012)
HK2125 (0805)	0.85 (0.033)	1.5±0.2 (0.059±0.008)	2.3±0.2 (0.091±0.008)	4.0±0.1 (0.157±0.004)	1.5 (0.059)	0.3 (0.012)
	1.0 (0.039)				2.0 (0.079)	
BK2125 (0805)	1.25 (0.049)	1.5±0.2 (0.059±0.008)	2.3±0.2 (0.091±0.008)	4.0±0.1 (0.157±0.004)	2.0 (0.079)	0.3 (0.012)
BK3216 (1206)	0.8 (0.031)	1.9±0.1 (0.075±0.004)	3.5±0.1 (0.138±0.004)	4.0±0.1 (0.157±0.004)	1.4 (0.055)	0.3 (0.012)
MCF0806 (0302)	0.4 (0.016)	0.75±0.05 (0.030±0.002)	0.95±0.05 (0.037±0.002)	2.0±0.05 (0.079±0.002)	0.55 (0.022)	0.3 (0.012)
MCF1210 (0504)	0.55 (0.022)	1.15±0.05 (0.045±0.002)	1.40±0.05 (0.055±0.002)	4.0±0.1 (0.157±0.004)	0.65 (0.026)	0.3 (0.012)
MCF2010 (0804)	0.45 (0.018)	1.1±0.1 (0.043±0.004)	2.3±0.1 (0.091±0.004)	4.0±0.1 (0.157±0.004)	0.85 (0.033)	0.3 (0.012)
MCKK1608 (0603)	1.0 (0.039)	1.1±0.1 (0.043±0.004)	1.95±0.1 (±0.004)	4.0±0.1 (0.157±0.004)	1.4 (0.055)	0.25 (0.01)
MCKK2012 (0805)	1.0 (0.039)	1.55±0.2 (0.061±0.008)	2.3±0.2 (0.091±0.008)	4.0±0.1 (0.157±0.004)	1.35 (0.053)	0.25 (0.010)

Unit : mm (inch)

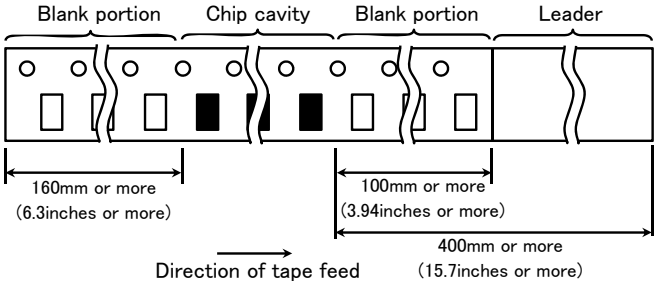
Embossed Tape (4mm wide)　　Unit : mm (inch)



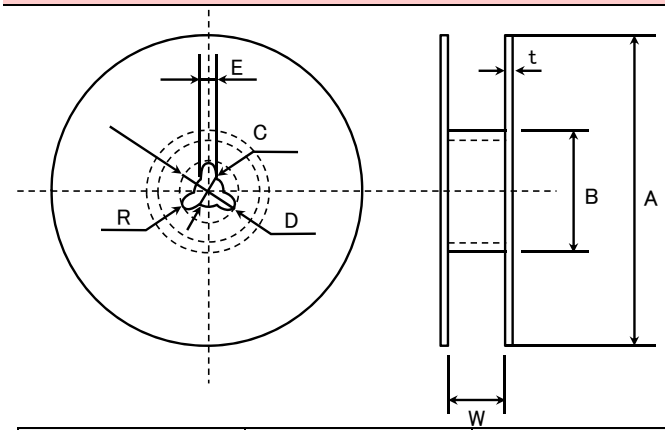
Type	Thickness mm (inch)	Chip cavity		Insertion Pitch	Tape Thickness	
		A	B	F	K	T
HKQ0402 (01005)	0.2 (0.008)	0.23	0.43	1.0±0.02	0.5max.	0.25max.

Unit : mm

④LEADER AND BLANK PORTION



⑤Reel Size



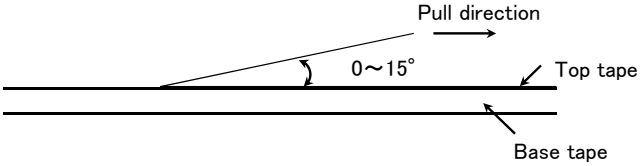
A	B	C	D	E	R
φ178±2.0	φ50 or more	φ13.0±0.2	φ21.0±0.8	2.0±0.5	1.0

	t	W
4mm width tape	1.5max.	5±1.0
8mm width tape	2.5max.	10±1.5

(Unit : mm)

⑥Top tape strength

The top tape requires a peel-off force of 0.1～0.7N in the direction of the arrow as illustrated below.



Multilayer chip inductors
Multilayer chip inductors for high frequency, Multilayer chip bead inductors
Multilayer common mode choke coils (MC series F type)
Metal Multilayer Chip Power Inductors (MCOIL™ MC series)

■RELIABILITY DATA

1. Operating Temperature Range			
Specified Value	BK0402		−55～＋125℃
	BK0603		
	BK1005		
	BKH0603		
	BKH1005		
	BK1608		
	BK2125		
	ARRAY	BK2010	
		BK3216	
	BKP0402		−55～＋85℃
	BKP0603		
	BKP1005		
	BKP1608		
	BKP2125		
	MCF 0605		−40～＋85℃
	MCF 0806		
	MCF 1210		
	MCF 2010		
	CK1608		−40～＋85℃
	CK2125		
	CKS2125		
	CKP1608		
	CKP2012		
	CKP2016		
	CKP2520		
	NM2012		
	NM2520		
	LK1005		
	LK1608		
	LK2125		
	HKQ0402		−55～＋125℃
	HK0603		
	HK1005		
	HK1608		−40～＋85℃
	HK2125		
	HKQ0603W/HKQ0603S/HKQ0603U		−55～＋125℃
	AQ105		
	MCFK1608		
	MCFE1608		−40～＋125℃ (Including self-generated heat)
	MCKK1608		
	MCHK2012		
	MCKK2012		

2. Storage Temperature Range			
Specified Value	BK0402		−55～＋125℃
	BK0603		
	BK1005		
	BKH0603		
	BKH1005		
	BK1608		
	BK2125		
	ARRAY	BK2010	
		BK3216	
	BKP0402		−55～＋85℃
	BKP0603		
	BKP1005		
	BKP1608		
	BKP2125		
	MCF 0605		−40～＋85℃
	MCF 0806		
	MCF 1210		
	MCF 2010		
	CK1608		−40～＋85℃
	CK2125		
	CKS2125		
	CKP1608		
	CKP2012		
	CKP2016		
	CKP2520		
	NM2012		
	NM2520		
	LK1005		
	LK1608		
	LK2125		
	HKQ0402		−55～＋125℃
	HK0603		
	HK1005		
	HK1608		−40～＋85℃
	HK2125		
	HKQ0603W/HKQ0603S/HKQ0603U		−55～＋125℃
	AQ105		
	MCFK1608		
	MCFE1608		−40～＋85℃
	MCKK1608		
	MCHK2012		
	MCKK2012		

3. Rated Current			
Specified Value	BK0402		150～750mA DC
	BK0603		100～500mA DC
	BK1005		120～1000mA DC
	BKH0603		115～450mA DC
	BKH1005		200～300mA DC
	BK1608		150～1500mA DC
	BK2125		200～1200mA DC
	ARRAY	BK2010	100mA DC
		BK3216	100～200mA DC
	BKP0402		0.55～1.1A DC
	BKP0603		0.8～1.8A DC
	BKP1005		0.8～2.4A DC
	BKP1608		1.0～3.0A DC
	BKP2125		1.5～4.0A DC
	MCF 0605		0.05A DC
	MCF 0806		0.1～0.13A DC
	MCF 1210		0.1～0.16A DC
	MCF 2010		0.1A DC
	CK1608		50～60mA DC
	CK2125		60～500mA DC
	CKS2125		110～280mA DC
	CKP1608		0.35～0.9A DC
	CKP2012		0.7～1.7A DC
	CKP2016		0.9～1.6A DC
	CKP2520		1.1～1.8A DC
	NM2012		1.0～1.2A DC
	NM2520		0.9～1.2A DC
	LK1005		20～25mA DC
	LK1608		1～150mA DC
	LK2125		5～300mA DC
	HK0603		60～470mA DC
	HK1005		110～300mA DC (−55～+125℃) 200～900mA DC (−55～+85℃)
	HK1608		150～300mA DC
	HK2125		300mA DC
	HKQ0402		100～500mA DC
	HKQ0603W		100～850mA DC
	HKQ0603S		130～600mA DC
	HKQ0603U		190～900mA DC
	AQ105		280～710mA DC
	MCFK1608		Idc1 : 1500～2300mA DC, Idc2 : 900～2100mA DC
	MCFE1608		Idc1 : 1400～2600mA DC, Idc2 : 800～1500mA DC
	MCKK1608		Idc1 : 2800～2000mA DC Idc2 : 1300～2600mA DC
	MCHK2012		Idc1 : 2260～4320mA DC, Idc2 : 1470～3600mA DC
	MCKK2012		Idc1 : 3600～6200mA DC, Idc2 : 2100～4000mA DC

Definition of rated current:

・In the CK, CKS and BK Series, the rated current is the value of current at which the temperature of the element is increased within 20℃.

・In the BK Series P type, CK Series P type, NM Series, the rated current is the value of current at which the temperature of the element is increased within 40℃.

・In the LK, HK, HKQ0603, and AQ Series, the rated current is either the DC value at which the initial L value is decreased within 5% with the application of DC bias, or the value of current at which the temperature of the element is increased within 20℃.

・In the HKQ0402(～9N1), the rated current is either the DC value at which the initial L value is decreased within 5% with the application of DC bias, or the value of current at which the temperature of the element is increased within 20℃.

・In the HKQ0402(10N～), the rated current is either the DC value at which the initial L value is decreased within 5% with the application of DC bias, or the value of current at which the temperature of the element is increased within 25℃.

・In the MC Series, Idc1 is the DC value at which the initial L value is decreased within 30% and Idc2 is the DC value at which the temperature of element is increased within 40℃ by the application of DC bias. (at 20℃)

4. Impedance			
Specified Value	BK0402		10～330Ω ±5Ω(10Ω), ±25%(Other)
	BK0603		10～1200Ω ±25%
	BK1005		10～1800Ω ±25%
	BKH0603		25～1500Ω ±25%
	BKH1005		600～1800Ω ±25%
	BK1608		22～2500Ω ±25%
	BK2125		15～2500Ω ±25%
	ARRAY	BK2010	5～1000Ω ±25%
		BK3216	60～1000Ω ±25%
	BKP0402		10～33Ω ±5Ω(10Ω)、±25%(Other)
	BKP0603		10～120Ω ±5Ω(10Ω), ±25%(Other)
	BKP1005		10～330Ω ±5Ω(EM100), ±25%(Other)
	BKP1608		33～470Ω ±25%
	BKP2125		33～330Ω ±25%
	MCF 0605		12～90Ω ±5Ω(12Ω), ±20%(35Ω90Ω),±25%(60Ω)
	MCF 0806		12～90Ω ±5Ω(12Ω), ±20%(47Ω90Ω),±25%(30Ω)
	MCF 1210		40～90Ω ±20%(2H900),±25%(Other)
	MCF 2010		90Ω ±25%
	CK1608		–
	CK2125		
	CKS2125		
	CKP1608		
	CKP2012		
	CKP2016		
	CKP2520		
	NM2012		
	NM2520		
	LK1005		
	LK1608		
	LK2125		
	HKQ0402		
	HK0603		
	HK1005		
	HK1608		
	HK2125		
	HKQ0603W/HKQ0603S/HKQ0603U		
	AQ105		
	MCFK1608		
	MCFE1608		
	MCKK1608		
	MCHK2012		
	MCKK2012		
Test Methods and Remarks	BK0402Series, BKP0402Series Measuring frequency : 100±1MHz Measuring equipment : E4991A(or its equivalent) Measuring jig : 16197A(or its equivalent) BK0603Series, BKP0603Series Measuring frequency : 100±1MHz Measuring equipment : 4291A(or its equivalent) Measuring jig : 16193A(or its equivalent) BK1005Series, BKP1005Series ,BKH1005Series Measuring frequency : 100±1MHz Measuring equipment : 4291A(or its equivalent) Measuring jig : 16192A(or its equivalent), 16193A(or its equivalent) BK1608・2125Series, BKP1608・2125Series Measuring frequency : 100±1MHz Measuring equipment : 4291A(or its equivalent), 4195A(or its equivalent) Measuring jig : 16092A(or its equivalent) or 16192A(or its equivalent)/HW BK2010・3216Series, MCF Series Measuring frequency : 100±1MHz Measuring equipment : 4291A(or its equivalent), 4195A(or its equivalent) Measuring jig : 16192A(or its equivalent)		

5. Inductance

Specified Value	BK0402		—
	BK0603		
	BK1005		
	BKH0603		
	BKH1005		
	BK1608		
	BK2125		
	ARRAY	BK2010	
		BK3216	
	BKP0402		
	BKP0603		
	BKP1005		
	BKP1608		
	BKP2125		
	MCF 0605		
	MCF 0806		
	MCF 1210		
	MCF 2010		
	CK1608		4.7～10.0 μH: ±20%
	CK2125		0.1～10.0 μH: ±20%
	CKS2125		1.0～10.0 μH: ±20%
	CKP1608		0.33～2.2 μH: ±20%
	CKP2012		0.47～4.7 μH: ±20%
	CKP2016		0.47～4.7 μH: ±20%
	CKP2520		0.47～4.7 μH: ±20%
	NM2012		0.82～1.0 μH: ±20%
	NM2520		1.0～2.2 μH: ±20%
	LK1005		0.12～2.2 μH: ±10 or 20%
	LK1608		0.047～33.0 μH: ±20%　0.10～12.0 μH: ±10%
	LK2125		0.047～33.0 μH: ±20%　0.10～12.0 μH: ±10%
	HK0603		1.0～6.2nH: ±0.3nH　6.8～100nH: ±5%
	HK1005		1.0～6.2nH: ±0.3nH　6.8～270nH: ±5%
	HK1608		1.0～5.6nH: ±0.3nH　6.8～470nH: ±5%
	HK2125		1.5～5.6nH: ±0.3nH　6.8～470nH: ±5%
	HKQ0402		0.5～3.9nH: ±0.1 or 0.2 or 0.3nH　4.3～5.6nH: ±0.3nH or 3% or 5% 6.2～47nH: ±3 or 5%
	HKQ0603W		0.6～3.9nH: ±0.1 or 0.2 or 0.3nH　4.3～6.2nH: ±0.2 or 0.3nH or 3 or 5% 6.8～30nH: ±3 or 5%　33～100nH: ±5%
	HKQ0603S		0.6～6.2nH: ±0.2 or 0.3nH　6.8～22nH: ±3 or 5%
	HKQ0603U		0.6～4.2nH: ±0.1 or 0.2 or 0.3nH　4.3～6.5nH: ±0.2 or 0.3nH　6.8～22nH: ±3 or 5%
	AQ105		1.0～6.2nH: ±0.3nH　6.8～15nH: ±5%
	MCFK1608		0.24～1.0 μH: ±20%
	MCFE1608		0.24～1.0 μH: ±20%
	MCKK1608		0.24～1.0 μH: ±20%
	MCHK2012		0.24～1.0 μH: ±20%
	MCKK2012		0.24～1.0 μH: ±20%

Test Methods and Remarks

CK、LK、CKP、NM、MC Series

- Measuring frequency : 2～4MHz(CK1608)
- Measuring frequency : 2～25MHz(CK2125)
- Measuring frequency : 2～10MHz(CKS2125)
- Measuring frequency : 10～25MHz(LK1005)
- Measuring frequency : 1～50MHz(LK1608)
- Measuring frequency : 0.4～50MHz(LK2125)
- Measuring frequency : 1MHz(CKP1608・CKP2012・CKP2016・CKP2520・NM2012・NM2520・MCFK1608・MCFE1608・MCHK2012・MCKK2012)
- Measuring equipment /jig :・4194A＋16085B＋16092A(or its equivalent)　・4195A＋41951＋16092A(or its equivalent)
  ・4294A＋16192A(or its equivalent)　・4291A＋16193A(or its equivalent)/LK1005
  ・4285A＋42841A＋42842C＋42851－61100(or its equivalent)/CKP1608・CKP2012・CKP2016・CKP2520・NM2012・NM2520・MCFK1608・MCFE1608・MCKK1608・MCHK2012・MCKK2012
- Measuring current :・1mA rms(0.047～4.7 μH)
  ・0.1mA rms(5.6～33 μH)

HK、HKQ、AQ Series

- Measuring frequency : 100MHz(HK0603・HK1005・AQ105)
- Measuring frequency : 50/100MHz(HK1608・HK2125)
- Measuring frequency : 500MHz(HKQ0603S・HKQ0603U)
- Measuring frequency : 300/500MHz(HKQ0603W)
- Measuring frequency : 100/500MHz(HKQ0402)
- Measuring equipment /jig :・4291A＋16197A(or its equivalent)/HK0603・AQ105
  ・4291A＋16193A(or its equivalent)/HK1005
  ・E4991A＋16197A(or its equivalent)/HKQ0603S・HKQ0603U・HKQ0603W
  ・4291A＋16092A ＋ in-house made jig(or its equivalent)/HK1608・HK2125
  ・E4991A＋16196D(or its equivalent)/HKQ0402

6. Q			
Specified Value	BK0402		—
	BK0603		
	BK1005		
	BKH0603		
	BKH1005		
	BK1608		
	BK2125		
	ARRAY	BK2010	
		BK3216	
	BKP0402		
	BKP0603		
	BKP1005		
	BKP1608		
	BKP2125		
	MCF 0605		
	MCF 0806		
	MCF 1210		
	MCF 2010		
	CK1608		—
	CK2125		
	CKS2125		
	CKP1608		
	CKP2012		
	CKP2016		
	CKP2520		
	NM2012		
	NM2520		
	LK1005		10～20 min.
	LK1608		10～35 min.
	LK2125		15～50 min.
	HK0603		4～5 min.
	HK1005		8 min.
	HK1608		8～12 min.
	HK2125		10～18 min.
	HKQ0402		3～8 min.
	HKQ0603W		6～15 min.
	HKQ0603S		10～13 min.
	HKQ0603U		14 min.
	AQ105		8 min.
	MCFK1608		—
	MCFE1608		
	MCKK1608		
	MCHK2012		
	MCKK2012		

Test Methods and Remarks

LK Series

Measuring frequency	: 10～25MHz(LK1005)
Measuring frequency	: 1～50MHz(LK1608)
Measuring frequency	: 0.4～50MHz(LK2125)
Measuring equipment /jig	:・4194A＋16085B＋16092A(or its equivalent)
	・4195A＋41951＋16092A(or its equivalent)
	・4294A＋16192A(or its equivalent)
	・4291A＋16193A(or its equivalent)/LK1005
Measuring current	・1mA rms(0.047～4.7 μH)
	・0.1mA rms(5.6～33 μH)

HK、HKQ、AQ Series

Measuring frequency	: 100MHz(HK0603・HK1005・AQ105)
Measuring frequency	: 50/100MHz(HK1608・HK2125)
Measuring frequency	: 500MHz(HKQ0603S・HKQ0603U)
Measuring frequency	: 300/500MHz(HKQ0603W)
Measuring frequency	: 100/500MHz(HKQ0402)
Measuring equipment /jig	:・4291A＋16197A(or its equivalent)/HK0603・AQ105
	・4291A＋16193A(or its equivalent)/HK1005
	・E4991A＋16197A(or its equivalent)/HKQ0603S・HKQ0603U・HKQ0603W
	・4291A＋16092A ＋ in-house made jig(or its equivalent)/HK1608, HK2125
	・E4991A＋16196D(or its equivalent)HKQ0402

7. DC Resistance			
Specified Value	BK0402		0.07～1.2Ω max.
	BK0603		0.065～1.50Ω max.
	BK1005		0.03～0.90Ω max.
	BKH0603		0.26～3.20Ω max.
	BKH1005		0.85～2.00Ω max.
	BK1608		0.05～1.10Ω max.
	BK2125		0.05～0.75Ω max.
	ARRAY	BK2010	0.10～0.90Ω max.
		BK3216	0.15～0.80Ω max.
	BKP0402		0.05～0.15Ω max.
	BKP0603		0.030～0.180Ω max.
	BKP1005		0.0273～0.220Ω max.
	BKP1608		0.025～0.18Ω max.
	BKP2125		0.020～0.075Ω max.
	MCF 0605		2.5～5.0Ω max
	MCF 0806		1.5～5.0Ω max.
	MCF 1210		1.5～4.5Ω max.
	MCF 2010		4.5Ω max.
	CK1608		0.45～0.85Ω(±30%)
	CK2125		0.16～0.65Ω max.
	CKS2125		0.12～0.52Ω max.
	CKP1608		0.15～0.35Ω max.
	CKP2012		0.08～0.28Ω max.
	CKP2016		0.075～0.20Ω max
	CKP2520		0.05～0.16Ω max.
	NM2012		0.10～0.15Ω max.
	NM2520		0.11～0.22Ω max.
	LK1005		0.41～1.16Ω max.
	LK1608		0.2～2.2Ω max.
	LK2125		0.1～1.1Ω max.
	HK0603		0.11～3.74Ω max.
	HK1005		0.08～4.8Ω max.
	HK1608		0.05～2.6Ω max.
	HK2125		0.10～1.5Ω max.
	HKQ0402		0.08～5.0Ω max.
	HKQ0603W		0.07～4.1Ω max.
	HKQ0603S		0.06～1.29Ω max.
	HKQ0603U		0.06～1.29Ω max.
	AQ105		0.07～0.45Ω max.
	MCFK1608		0.050～0.224Ω max.
	MCFE1608		0.100～0.340Ω max.
	MCKK1608		0.038～0.123Ω max.
	MCHK2012		0.024～0.111Ω max.
	MCKK2012		0.025～0.090Ω max.
Test Methods and Remarks	Measuring equipment：VOAC-7412, VOAC-7512, VOAC-7521（made by Iwasaki Tsushinki）, HIOKI3227 (or its equivalent)		

8. Self Resonance Frequency (SRF)			
Specified Value	BK0402		—
	BK0603		
	BK1005		
	BKH0603		
	BKH1005		
	BK1608		
	BK2125		
	ARRAY	BK2010	
		BK3216	
	BKP0402		
	BKP0603		
	BKP1005		
	BKP1608		
	BKP2125		
	MCF 0605		
	MCF 0806		
	MCF 1210		
	MCF 2010		
	CK1608		17～25MHz min.
	CK2125		24～235MHz min.
	CKS2125		24～75MHz min.
	CKP1608		—
	CKP2012		
	CKP2016		
	CKP2520		
	NM2012		
	NM2520		
	LK1005		40～180MHz min.
	LK1608		9～260MHz min.
	LK2125		13～320MHz min.
	HK0603		900～10000MHz min.
	HK1005		400～10000MHz min.
	HK1608		300～10000MHz min.
	HK2125		200～4000MHz min.
	HKQ0402		1200～10000MHz min.
	HKQ0603W		800～10000MHz min.
	HKQ0603S		1900～10000MHz min.
	HKQ0603U		1900～10000MHz min.
	AQ105		2300～10000MHz min.
	MCFK1608		—
	MCFE1608		
	MCKK1608		
	MCHK2012		
	MCKK2012		
Test Methods and Remarks	LK、CK Series : Measuring equipment : 4195A (or its equivalent) Measuring jig : 41951＋16092A (or its equivalent) HK、HKQ、AQ Series : Measuring equipment : 8719C (or its equivalent)・8753D (or its equivalent)/HK2125		

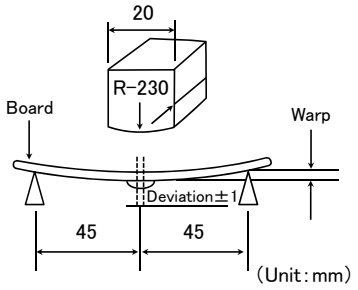
9. Temperature Characteristic		
Specified Value	BK0402	–
	BK0603	
	BK1005	
	BKH0603	
	BKH1005	
	BK1608	
	BK2125	
	ARRAY: BK2010	
	ARRAY: BK3216	
	BKP0402	
	BKP0603	
	BKP1005	
	BKP1608	
	BKP2125	
	MCF 0605	
	MCF 0806	
	MCF 1210	
	MCF 2010	
	CK1608	
	CK2125	
	CKS2125	
	CKP1608	
	CKP2012	
	CKP2016	
	CKP2520	
	NM2012	
	NM2520	
	LK1005	
	LK1608	
	LK2125	
	HK0603	Inductance change : Within ±10%
	HK1005	
	HK1608	
	HK2125	
	HKQ0402	
	HKQ0603W	
	HKQ0603S	
	HKQ0603U	
	AQ105	
	MCFK1608	
	MCFE1608	
	MCKK1608	
	MCHK2012	
	MCKK2012	
Test Methods and Remarks	HK、HKQ、AQ Series: Temperature range : −30～+85℃ Reference temperature : +20℃ MC Series: Temperature range : −40～+85℃ Reference temperature : +20℃	

10. Resistance to Flexure of Substrate

Specified Value	BK0402		No mechanical damage.
	BK0603		
	BK1005		
	BKH0603		
	BKH1005		
	BK1608		
	BK2125		
	ARRAY	BK2010	
		BK3216	
	BKP0402		
	BKP0603		
	BKP1005		
	BKP1608		
	BKP2125		
	MCF 0605		
	MCF 0806		
	MCF 1210		
	MCF 2010		
	CK1608		
	CK2125		
	CKS2125		
	CKP1608		
	CKP2012		
	CKP2016		
	CKP2520		
	NM2012		
	NM2520		
	LK1005		
	LK1608		
	LK2125		
	HK0603		
	HK1005		
	HK1608		
	HK2125		
	HKQ0402		
	HKQ0603W		
	HKQ0603S		
	HKQ0603U		
	AQ105		
	MCFK1608		
	MCFE1608		
	MCKK1608		
	MCHK2012		
	MCKK2012		

Test Methods and Remarks

Warp : 2mm(BK Series without 0402size、BKP、BKH1005、CK、CKS、CKP、LK、HK、HKQ0603S、HKQ0603U、AQ Series、MCF1210、MC Series)
: 1mm(BK0402、BKP0402、BKH0603、HKQ0402、HKQ0603W、MCF Series without 1210 size,)
Testing board : glass epoxy-resin substrate
Thickness : 0.8mm



11. Solderability			
Specified Value	BK0402		At least 90% of terminal electrode is covered by new solder.
	BK0603		
	BK1005		
	BKH0603		
	BKH1005		
	BK1608		
	BK2125		
	ARRAY	BK2010	
		BK3216	
	BKP0402		
	BKP0603		
	BKP1005		
	BKP1608		
	BKP2125		
	MCF 0605		
	MCF 0806		
	MCF 1210		
	MCF 2010		
	CK1608		
	CK2125		
	CKS2125		
	CKP1608		
	CKP2012		
	CKP2016		
	CKP2520		
	NM2012		
	NM2520		
	LK1005		
	LK1608		
	LK2125		
	HK0603		
	HK1005		
	HK1608		
	HK2125		
	HKQ0402		
	HKQ0603W		
	HKQ0603S		
	HKQ0603U		
	AQ105		
	MCFK1608		
	MCFE1608		
	MCKK1608		
	MCHK2012		
	MCKK2012		
Test Methods and Remarks	Solder temperature	:230±5℃ (JIS Z 3282 H60A or H63A)	
	Solder temperature	:245±3℃ (Sn/3.0Ag/0.5Cu)	
	Duration	:4±1 sec.	

12. Resistance to Soldering			
Specified Value	BK0402		Appearance：No significant abnormality Impedance change：Within ±30%
	BK0603		
	BK1005		
	BKH0603		
	BKH1005		
	BK1608		
	BK2125		
	ARRAY	BK2010	
		BK3216	
	BKP0402		
	BKP0603		
	BKP1005		
	BKP1608		
	BKP2125		
	MCF 0605		Appearance：No significant abnormality Impedance change：Within ±20%
	MCF 0806		
	MCF 1210		
	MCF 2010		
	CK1608		Appearance：No significant abnormality Inductance change R10～4R7： Within ±10% 6R8～100： Within ±15% CKS2125 ： Within ±20% CKP1608、CKP2012、CKP2016、CKP2520、NM2012、NM2520： Within ±30%
	CK2125		
	CKS2125		
	CKP1608		
	CKP2012		
	CKP2016		
	CKP2520		
	NM2012		
	NM2520		
	LK1005		Appearance：No significant abnormality Inductance change： Within ±15%
	LK1608		Appearance：No significant abnormality Inductance change 47N～4R7： Within ±10% 5R6～330： Within ±15%
	LK2125		
	HK0603		Appearance：No significant abnormality Inductance change： Within ±5%
	HK1005		
	HK1608		
	HK2125		
	HKQ0402		
	HKQ0603W		
	HKQ0603S		
	HKQ0603U		
	AQ105		
	MCFK1608		Appearance：No significant abnormality Inductance change： Within ±10%
	MCFE1608		
	MCKK1608		
	MCHK2012		
	MCKK2012		
Test Methods and Remarks	Solder temperature	：260±5℃	
	Duration	：10±0.5 sec.	
	Preheating temperature	：150 to 180℃	
	Preheating time	：3 min.	
	Flux	：Immersion into methanol solution with colophony for 3 to 5 sec.	
	Recovery	：2 to 3 hrs of recovery under the standard condition after the test.(See Note 1)	
(Note 1) When there are questions concerning measurement result；measurement shall be made after 48±2 hrs of recovery under the standard condition.			

13. Thermal Shock

Specified Value

BK0402		Appearance：No significant abnormality Impedance change： Within ±30%
BK0603		
BK1005		
BKH0603		
BKH1005		
BK1608		
BK2125		
ARRAY	BK2010	
	BK3216	
BKP0402		
BKP0603		
BKP1005		
BKP1608		
BKP2125		
MCF 0605		Appearance：No significant abnormality Impedance change： Within ±20%
MCF 0806		
MCF 1210		
MCF 2010		
CK1608		Appearance：No significant abnormality Inductance change：Within ±20% Q change：Within ±30%
CK2125		
CKS2125		Appearance：No significant abnormality Inductance change：Within ±20%
CKP1608		Appearance：No significant abnormality Inductance change： Within ±30%
CKP2012		
CKP2016		
CKP2520		
NM2012		
NM2520		
LK1005		Appearance：No significant abnormality Inductance change： Within ±10% Q change： Within ±30%
LK1608		
LK2125		
HK0603		Appearance：No significant abnormality Inductance change： Within ±10% Q change： Within ±20%
HK1005		
HK1608		
HK2125		
HKQ0402		
HKQ0603W		
HKQ0603S		
HKQ0603U		
AQ105		
MCFK1608		Appearance：No significant abnormality Inductance change： Within ±10%
MCFE1608		
MCKK1608		
MCHK2012		
MCKK2012		

Test Methods and Remarks

Conditions for 1 cycle

Step	temperature(℃)	time(min.)
1	Minimum operating temperature +0/−3	30±3
2	Room temperature	2～3
3	Maximum operating temperature +3/−0	30±3
4	Room temperature	2～3

Number of cycles：5

Recovery：2 to 3 hrs of recovery under the standard condition after the test.(See Note 1)

(Note 1) When there are questions concerning measurement result；measurement shall be made after 48±2 hrs of recovery under the standard condition.

14. Damp Heat(Steady state)			
Specified Value	BK0402		Appearance:No significant abnormality Impedance change: Within ±30%
	BK0603		
	BK1005		
	BKH0603		
	BKH1005		
	BK1608		
	BK2125		
	ARRAY	BK2010	
		BK3216	
	BKP0402		
	BKP0603		
	BKP1005		
	BKP1608		
	BKP2125		
	MCF 0605		Appearance:No significant abnormality Impedance change: Within ±20%
	MCF 0806		
	MCF 1210		
	MCF 2010		
	CK1608		Appearance:No significant abnormality Inductance change: Within ±20% Q change: Within ±30%
	CK2125		
	CKS2125		Appearance:No significant abnormality Inductance change: Within ±20%
	CKP1608		Appearance:No significant abnormality Inductance change: Within ±30%
	CKP2012		
	CKP2016		
	CKP2520		
	NM2012		
	NM2520		
	LK1005		Appearance:No significant abnormality Inductance change: Within ±10% Q change: Within ±30%
	LK1608		
	LK2125		Appearance:No significant abnormality Inductance change: Within ±20% Q change: Within ±30%
	HK0603		Appearance:No significant abnormality Inductance change: Within ±10% Q change: Within ±20%
	HK1005		
	HK1608		
	HK2125		
	HKQ0402		
	HKQ0603W		
	HKQ0603S		
	HKQ0603U		
	AQ105		
	MCFK1608		Appearance:No significant abnormality Inductance change: Within ±10%
	MCFE1608		
	MCKK1608		
	MCHK2012		
	MCKK2012		
Test Methods and Remarks	BK、BKP、BKH、LK、CK、CKS、CKP、NM Series、MCF Series: Temperature :40±2℃ Humidity :90 to 95%RH Duration :500 +24/−0 hrs Recovery :2 to 3 hrs of recovery under the standard condition after the removal from test chamber.(See Note 1) HK、HKQ、AQ、MC Series: Temperature :60±2℃ Humidity :90 to 95%RH Duration :500 +24/−0 hrs Recovery :2 to 3 hrs of recovery under the standard condition after the removal from test chamber.(See Note 1)		

(Note 1) When there are questions concerning measurement result;measurement shall be made after 48±2 hrs of recovery under the standard condition.

15. Loading under Damp Heat			
Specified Value	BK0402		Appearance：No significant abnormality Impedance change： Within ±30%
	BK0603		
	BK1005		
	BKH0603		
	BKH1005		
	BK1608		
	BK2125		
	ARRAY	BK2010	
		BK3216	
	BKP0402		
	BKP0603		
	BKP1005		
	BKP1608		
	BKP2125		
	CK1608		Appearance：No significant abnormality Inductance change： Within ±20% Q change： Within ±30%
	CK2125		
	CKS2125		Appearance：No significant abnormality Inductance change： Within ±20%
	CKP1608		Appearance：No significant abnormality Inductance change： Within ±30%
	CKP2012		
	CKP2016		
	CKP2520		
	NM2012		
	NM2520		
	LK1005		Appearance：No significant abnormality Inductance change： Within ±10% Q change： Within ±30%
	LK1608		Appearance：No significant abnormality Inductance change： 0.047～12.0 μH： Within ±10% 15.0～33.0 μH： Within ±15% Q change： Within ±30%
	LK2125		Appearance：No significant abnormality Inductance change： Within ±20% Q change： Within ±30%
	HK0603		Appearance：No significant abnormality Inductance change： Within ±10% Q change： Within ±20%
	HK1005		
	HK1608		
	HK2125		
	HKQ0402		
	HKQ0603W		
	HKQ0603S		
	HKQ0603U		
	AQ105		
	MCFK1608※		Appearance：No significant abnormality Inductance change： Within ±10%
	MCFE1608※		
	MCKK1608※		
	MCHK2012※		
	MCKK2012※		
Test Methods and Remarks	BK、BKP、BKH、LK、CK、CKS、CKP、NM Series： Temperature ：40±2℃ Humidity ：90 to 95%RH Applied current ：Rated current Duration ：500 +24/−0 hrs Recovery ：2 to 3 hrs of recovery under the standard condition after the removal from test chamber.(See Note 1) HK、HKQ、AQ、MC Series： Temperature ：60±2℃ Humidity ：90 to 95%RH Applied current ：Rated current ※MC series ; Idc2max Duration ：500 +24/−0 hrs Recovery ：2 to 3 hrs of recovery under the standard condition after the removal from test chamber.(See Note 1)		

Note on standard condition: "standard condition" referred to herein is defined as follows:
5 to 35℃ of temperature, 45 to 85% relative humidity, and 86 to 106kPa of air pressure.
When there are questions concerning measurement results:
In order to provide correlation data, the test shall be conducted under condition of 20±2℃ of temperature, 60 to 70% relative humidity, and 86 to 106kPa of air pressure.
Unless otherwise specified, all the tests are conducted under the "standard condition."
(Note 1) Measurement shall be made after 48±2 hrs of recovery under the standard condition.

16. Loading at High Temperature			
Specified Value	BK0402		Appearance：No significant abnormality Impedance change： Within ±30%
	BK0603		
	BK1005		
	BKH0603		
	BKH1005		
	BK1608		
	BK2125		
	ARRAY	BK2010	
		BK3216	
	BKP0402		
	BKP0603		
	BKP1005		
	BKP1608		
	BKP2125		
	MCF 0605		Appearance：No significant abnormality Impedance change： Within ±20%
	MCF 0806		
	MCF 1210		
	MCF 2010		
	CK1608		Appearance：No significant abnormality Inductance change： Within ±20% Q change： Within ±30%
	CK2125		
	CKS2125		Appearance：No significant abnormality Inductance change： Within ±20%
	CKP1608		Appearance：No significant abnormality Inductance change： Within ±30%
	CKP2012		
	CKP2016		
	CKP2520		
	NM2012		
	NM2520		
	LK1005		Appearance：No significant abnormality Inductance change： Within ±10% Q change： Within ±30%
	LK1608		Appearance：No significant abnormality Inductance change： 0.047～12.0 μH： Within ±10% 15.0～33.0 μH： Within ±15% Q change： Within ±30%
	LK2125		Appearance：No significant abnormality Inductance change： Within ±20% Q change： Within ±30%
	HK0603		Appearance：No significant abnormality Inductance change： Within ±10% Q change： Within ±20%
	HK1005		
	HK1608		
	HK2125		
	HKQ0402		
	HKQ0603W		
	HKQ0603S		
	HKQ0603U		
	AQ105		
	MCFK1608※		Appearance：No significant abnormality Inductance change： Within ±10%
	MCFE1608※		
	MCKK1608※		
	MCHK2012※		
	MCKK2012※		
Test Methods and Remarks	Temperature : Maximum operating temperature Applied current : Rated current ※MC series ; Idc2max Duration : 500 +24/−0 hrs Recovery : 2 to 3 hrs of recovery under the standard condition after the removal from test chamber. (See Note 1)		

Note on standard condition: "standard condition" referred to herein is defined as follows:
5 to 35℃ of temperature, 45 to 85% relative humidity, and 86 to 106kPa of air pressure.
When there are questions concerning measurement results:
In order to provide correlation data, the test shall be conducted under condition of 20±2℃ of temperature, 60 to 70% relative humidity, and 86 to 106kPa of air pressure. Unless otherwise specified, all the tests are conducted under the "standard condition."
(Note 1) Measurement shall be made after 48±2 hrs of recovery under the standard condition.

Precautions on the use of Multilayer chip inductors
Multilayer chip inductors for high frequency, Multilayer chip bead inductors
Multilayer common mode choke coils (MC series F type)
Metal Multilayer Chip Power Inductors (MCOIL™ MC series)

■PRECAUTIONS

1. Circuit Design

Precautions

◆Verification of operating environment, electrical rating and performance

1. A malfunction in medical equipment, spacecraft, nuclear reactors, etc. may cause serious harm to human life or have severe social ramifications.
   As such, any inductors to be used in such equipment may require higher safety and/or reliability considerations and should be clearly differentiated from components used in general purpose applications.

◆Operating Current (Verification of Rated current)

1. The operating current including inrush current for inductors must always be lower than their rated values.
2. Do not apply current in excess of the rated value because the inductance may be reduced due to the magnetic saturation effect.

2. PCB Design

Precautions

◆Pattern configurations (Design of Land-patterns)

1. When inductors are mounted on a PCB, the size of land patterns and the amount of solder used (size of fillet) can directly affect inductor performance.
   Therefore, the following items must be carefully considered in the design of solder land patterns:
   (1) The amount of solder applied can affect the ability of chips to withstand mechanical stresses which may lead to breaking or cracking. Therefore, when designing land-patterns it is necessary to consider the appropriate size and configuration of the solder pads which in turn determines the amount of solder necessary to form the fillets.
   (2) When more than one part is jointly soldered onto the same land or pad, the pad must be designed so that each component's soldering point is separated by solder-resist.
   (3) The larger size of land patterns and amount of solder, the smaller Q value after mounting on PCB. It makes higher the Q value to design land patterns smaller than terminal electrode of chips.

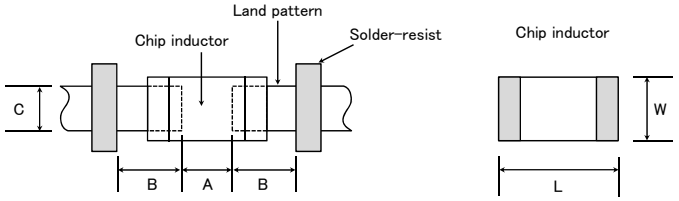
◆Pattern configurations (Inductor layout on panelized[breakaway] PC boards)

1. After inductors have been mounted on the boards, chips can be subjected to mechanical stresses in subsequent manufacturing processes (PCB cutting, board inspection, mounting of additional parts, assembly into the chassis, wave soldering the reflow soldered boards etc.) For this reason, planning pattern configurations and the position of SMD inductors should be carefully performed to minimize stress.

Technical considerations

◆Pattern configurations (Design of Land-patterns)

1. The following diagrams and tables show some examples of recommended patterns to prevent excessive solder amounts (larger fillets which extend above the component end terminations). Examples of improper pattern designs are also shown.
   (1) Recommended land dimensions for a typical chip inductor land patterns for PCBs



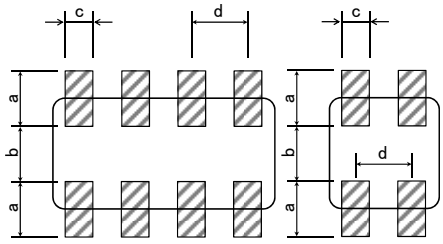
Recommended land dimensions for wave-soldering (Unit: mm)

Type		1608	2012	2125	2016	2520	3216
Size	L	1.6	2.0	2.0	2.0	2.5	3.2
	W	0.8	1.25	1.25	1.6	2.0	1.6
A		0.8～1.0	1.0～1.4	1.0～1.4	1.0～1.4	1.0～1.4	1.8～2.5
B		0.5～0.8	0.8～1.5	0.8～1.5	0.8～1.5	0.6～1.0	0.8～1.7
C		0.6～0.8	0.9～1.2	0.9～1.2	1.3～1.6	1.6～2.0	1.2～1.6

Recommended land dimensions for reflow-soldering (Unit: mm)

Type		0402	0603	1005	105	1608	2012	2125	2016	2520	3216
Size	L	0.4	0.6	1.0	1.0	1.6	2.0	2.0	2.0	2.5	3.2
	W	0.2	0.3	0.5	0.6	0.8	1.25	1.25	1.6	2.0	1.6
A		0.15～0.25	0.20～0.30	0.45～0.55	0.50～0.55	0.8～1.0	0.8～1.2	0.8～1.2	0.8～1.2	1.0～1.4	1.8～2.5
B		0.10～0.20	0.20～0.30	0.40～0.50	0.30～0.40	0.6～0.8	0.8～1.2	0.8～1.2	0.8～1.2	0.6～1.0	0.6～1.5
C		0.15～0.30	0.25～0.40	0.45～0.55	0.60～0.70	0.6～0.8	0.9～1.6	0.9～1.6	1.2～2.0	1.8～2.2	1.2～2.0

Excess solder can affect the ability of chips to withstand mechanical stresses. Therefore, please take proper precautions when designing land-patterns.

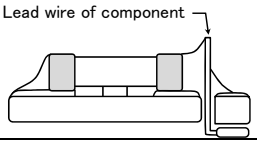
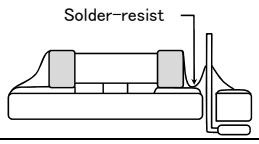
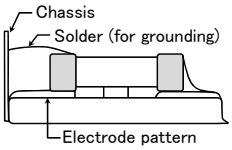
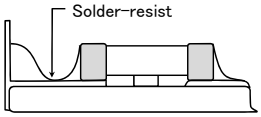
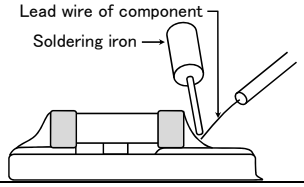
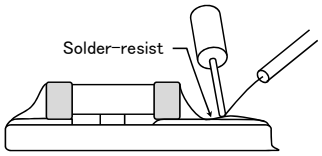
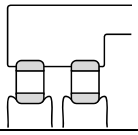
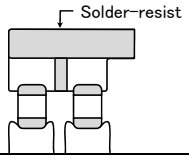


Recommended land dimension for Reflow-soldering

Type		3216	2010	1210	0806	0605
Size	L	3.2	2.0	1.25	0.85	0.65
	W	1.6	1.0	1.0	0.65	0.50
a		0.7～0.9	0.5～0.6	0.45～0.55	0.25～0.35	0.27～0.33
b		0.8～1.0	0.5～0.6	0.7～0.8	0.25～0.35	0.17～0.23
c		0.4～0.5	0.2～0.3	0.25～0.35	0.25～0.35	0.20～0.26
d		0.8	0.5	0.55	0.5	0.4

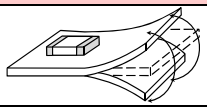
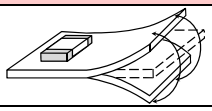
(Unit：mm)

((2) Examples of good and bad solder application

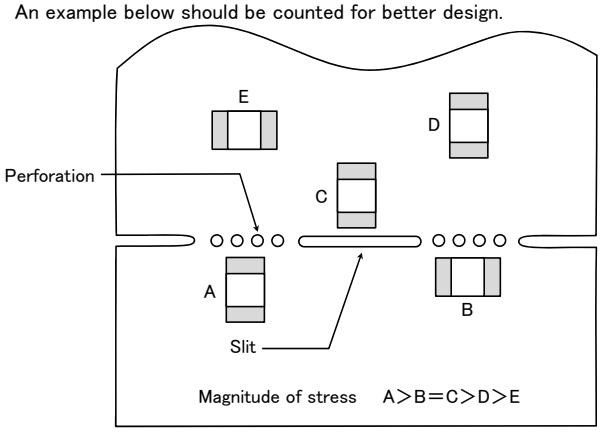
Item	Not recommended	Recommended
Mixed mounting of SMD and leaded components		
Component placement close to the chassis		
Hand-soldering of leaded components near mounted components		
Horizontal component placement		

◆Pattern configurations (Inductor layout on panelized[breakaway] PC boards)

1-1. The following are examples of good and bad inductor layout; SMD inductors should be located to minimize any possible mechanical stresses from board warp or deflection.

Item	Not recommended	Recommended
Deflection of the board		 Position the component at a right angle to the direction of the mechanical stresses that are anticipated.

1-2. To layout the inductors for the breakaway PC board, it should be noted that the amount of mechanical stresses given will vary depending on inductor layout.
An example below should be counted for better design.



1-3. When breaking PC boards along their perforations, the amount of mechanical stress on the inductors can vary according to the method used. The following methods are listed in order from least stressful to most stressful: push-back, slit, V-grooving, and perforation. Thus, any ideal SMD inductor layout must also consider the PCB splitting procedure.

3. Considerations for automatic placement

Precautions

◆Adjustment of mounting machine

1. Excessive impact load should not be imposed on the inductors when mounting onto the PC boards.
2. The maintenance and inspection of the mounter should be conducted periodically.

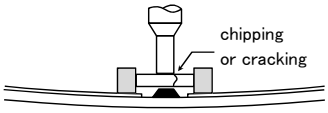
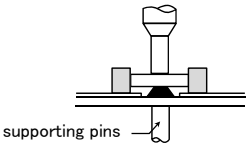
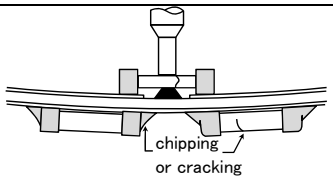
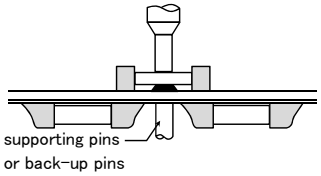
◆Selection of Adhesives

1. Mounting inductors with adhesives in preliminary assembly, before the soldering stage, may lead to degraded inductor characteristics unless the following factors are appropriately checked; the size of land patterns, type of adhesive, amount applied, hardening temperature and hardening period. Therefore, it is imperative to consult the manufacturer of the adhesives on proper usage and amounts of adhesive to use.

Technical considerations

◆Adjustment of mounting machine

1. If the lower limit of the pick-up nozzle is low, too much force may be imposed on the inductors, causing damage. To avoid this, the following points should be considered before lowering the pick-up nozzle:
   (1) The lower limit of the pick-up nozzle should be adjusted to the surface level of the PC board after correcting for deflection of the board.
   (2) The pick-up pressure should be adjusted between 1 and 3N static loads.
   (3) To reduce the amount of deflection of the board caused by impact of the pick-up nozzle, supporting pins or back-up pins should be used under the PC board. The following diagrams show some typical examples of good pick-up nozzle placement:

Item	Improper method	Proper method
Single-sided mounting		
Double-sided mounting		

2. As the alignment pin wears out, adjustment of the nozzle height can cause chipping or cracking of the inductors because of mechanical impact on the inductors. To avoid this, the monitoring of the width between the alignment pin in the stopped position, and maintenance, inspection and replacement of the pin should be conducted periodically.

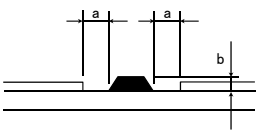
◆Selection of Adhesives

1. Some adhesives may cause reduced insulation resistance. The difference between the shrinkage percentage of the adhesive and that of the inductors may result in stresses on the inductors and lead to cracking. Moreover, too little or too much adhesive applied to the board may adversely affect component placement, so the following precautions should be noted in the application of adhesives.
   (1) Required adhesive characteristics
      a. The adhesive should be strong enough to hold parts on the board during the mounting & solder process.
      b. The adhesive should have sufficient strength at high temperatures.
      c. The adhesive should have good coating and thickness consistency.
      d. The adhesive should be used during its prescribed shelf life.
      e. The adhesive should harden rapidly.
      f. The adhesive must not be contaminated.
      g. The adhesive should have excellent insulation characteristics.
      h. The adhesive should not be toxic and have no emission of toxic gasses.
   (2) When using adhesives to mount inductors on a PCB, inappropriate amounts of adhesive on the board may adversely affect component placement. Too little adhesive may cause the inductors to fall off the board during the solder process. Too much adhesive may cause defective soldering due excessive flow of adhesive on to the land or solder pad.

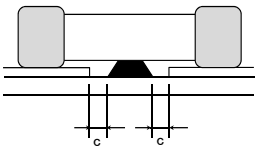
[Recommended conditions]

Figure	0805 case sizes as examples
a	0.3mm min
b	100～120 μm
c	Area with no adhesive

Amount of adhesives



After inductors are bonded



4. Soldering

Precautions

◆Selection of Flux

1. Since flux may have a significant effect on the performance of inductors, it is necessary to verify the following conditions prior to use;
   (1) Flux used should be with less than or equal to 0.1 wt% (Chlorine conversion method) of halogenated content. Flux having a strong acidity content should not be applied.
   (2) When soldering inductors on the board, the amount of flux applied should be controlled at the optimum level.
   (3) When using water-soluble flux, special care should be taken to properly clean the boards.

◆Soldering

1. Temperature, time, amount of solder, etc. are specified in accordance with the following recommended conditions, and please contact us about peak temperature when you use lead-free paste.

Technical considerations

◆Selection of Flux

1-1. When too much halogenated substance (Chlorine, etc.) content is used to activate the flux, or highly acidic flux is used, an excessive amount of residue after soldering may lead to corrosion of the terminal electrodes or degradation of insulation resistance on the surface of the Inductor.

1-2. Flux is used to increase solderability in flow soldering, but if too much is applied, a large amount of flux gas may be emitted and may detrimentally affect solderability. To minimize the amount of flux applied, it is recommended to use a flux-bubbling system.

1-3. Since the residue of water-soluble flux is easily dissolved by water content in the air, the residue on the surface of Inductor in high humidity conditions may cause a degradation of insulation resistance and therefore affect the reliability of the components. The cleaning methods and the capability of the machines used should also be considered carefully when selecting water-soluble flux.

◆Soldering

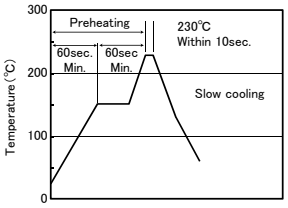
1-1. Preheating when soldering

Heating: Chip inductor components should be preheated to within 100 to 130℃ of the soldering. Cooling: The temperature difference between the components and cleaning process should not be greater than 100℃.

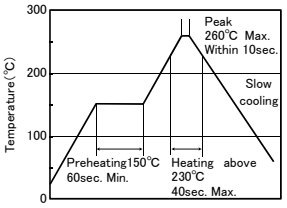
Chip inductors are susceptible to thermal shock when exposed to rapid or concentrated heating or rapid cooling. Therefore, the soldering process must be conducted with a great care so as to prevent malfunction of the components due to excessive thermal shock.

[Reflow soldering]

【Recommended conditions for eutectic soldering】



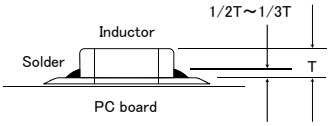
【Recommended condition for Pb-free soldering】



※Ceramic chip components should be preheated to within 100 to 130℃ of the soldering.
※Assured to be reflow soldering for 2 times.
※MC series; Peak 230℃(eutectic soldering)、260℃(Pb-free soldering)max within 5sec.

Caution

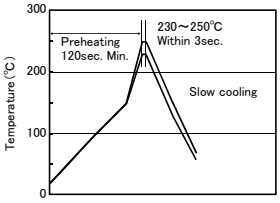
1. The ideal condition is to have solder mass (fillet) controlled to 1/2 to 1/3 of the thickness of the inductor, as shown below:



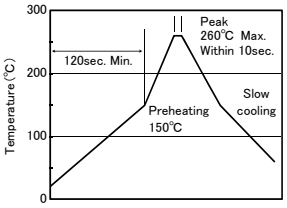
2. Because excessive dwell times can detrimentally affect solderability, soldering duration should be kept as close to recommended times as possible.

[Wave soldering]

【Recommended conditions for eutectic soldering】



【Recommended condition for Pb-free soldering】



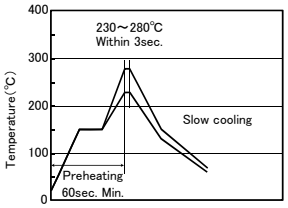
※Ceramic chip components should be preheated to within 100 to 130℃ of the soldering.
※Assured to be wave soldering for 1 time.
※Except for reflow soldering type.

Caution

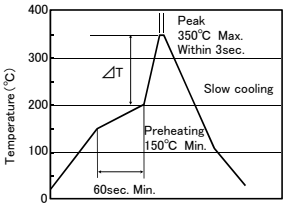
1. Make sure the inductors are preheated sufficiently.
2. The temperature difference between the inductor and melted solder should not be greater than 100 to 130℃.
3. Cooling after soldering should be as gradual as possible.
4. Wave soldering must not be applied to the inductors designated as for reflow soldering only.

[Hand soldering]

【Recommended conditions for eutectic soldering



【Recommended condition for Pb-free soldering】



(※⊿T≦190℃(3216Type max), ⊿T≦130℃(3225 Type min)
※It is recommended to use 20W soldering iron and the tip is 1φ or less.
※The soldering iron should not directly touch the components.
※Assured to be soldering iron for 1 time.
Note: The above profiles are the maximum allowable soldering condition, therefore these profiles are not always recommended.

	Caution 1. Use a 20W soldering iron with a maximum tip diameter of 1.0 mm. 2. The soldering iron should not directly touch the inductor.

5. Cleaning	
Precautions	◆Cleaning conditions 1. When cleaning the PC board after the Inductors are all mounted, select the appropriate cleaning solution according to the type of flux used and purpose of the cleaning(e.g. to remove soldering flux or other materials from the production process.) 2. Cleaning conditions should be determined after verifying, through a test run, that the cleaning process does not affect the inductor's characteristics.
Technical considerations	◆Cleaning conditions 1. The use of inappropriate solutions can cause foreign substances such as flux residue to adhere to the inductor, resulting in a degradation of the inductor's electrical properties(especially insulation resistance). 2. Inappropriate cleaning conditions(insufficient or excessive cleaning)may detrimentally affect the performance of the inductors. (1) Excessive cleaning a. In the case of ultrasonic cleaning, too much power output can cause excessive vibration of the PC board which may lead to the cracking of the inductor or the soldered portion, or decrease the terminal electrodes' strength. Thus the following conditions should be carefully checked; Ultrasonic output Below 20W/ℓ Ultrasonic frequency Below 40kHz Ultrasonic washing period 5 min. or less

6. Post cleaning processes	
Precautions	◆Application of resin coatings, moldings, etc. to the PCB and components. 1. With some type of resins a decomposition gas or chemical reaction vapor may remain inside the resin during the hardening period or while left under normal storage conditions resulting in the deterioration of the inductor's performance. 2. When a resin's hardening temperature is higher than the inductor's operating temperature, the stresses generated by the excess heat may lead to inductor damage or destruction. 3. Stress caused by a resin's temperature generated expansion and contraction may damage inductors. The use of such resins, molding materials etc. is not recommended.

7. Handling	
Precautions	◆Breakaway PC boards(splitting along perforations) 1. When splitting the PC board after mounting inductors and other components, care is required so as not to give any stresses of deflection or twisting to the board. 2. Board separation should not be done manually, but by using the appropriate devices. ◆General handling precautions 1. Always wear static control bands to protect against ESD. 2. Keep the inductors away from all magnets and magnetic objects. 3. Use non-magnetic tweezers when handling inductors. 4. Any devices used with the inductors(soldering irons, measuring instruments) should be properly grounded. 5. Keep bare hands and metal products(i.e., metal desk)away from chip electrodes or conductive areas that lead to chip electrodes. 6. Keep inductors away from items that generate magnetic fields such as speakers or coils. ◆Mechanical considerations 1. Be careful not to subject the inductors to excessive mechanical shocks. (1) If inductors are dropped on the floor or a hard surface they should not be used. (2) When handling the mounted boards, be careful that the mounted components do not come in contact with or bump against other boards or components.

8. Storage conditions	
Precautions	◆Storage 1. To maintain the solderability of terminal electrodes and to keep the packaging material in good condition, care must be taken to control temperature and humidity in the storage area. Humidity should especially be kept as low as possible. ・Recommended conditions Ambient temperature: Below 30℃ Humidity: Below 70% RH The ambient temperature must be kept below 40℃. Even under ideal storage conditions, solderability of inductor is deteriorated as time passes, so inductors should be used within 6 months from the time of delivery. ・Inductor should be kept where no chlorine or sulfur exists in the air.
Technical considerations	◆Storage 1. If the parts are stocked in a high temperature and humidity environment, problems such as reduced solderability caused by oxidation of terminal electrodes and deterioration of taping/packaging materials may take place. For this reason, components should be used within 6 months from the time of delivery. If exceeding the above period, please check solderability before using the inductors.

SMD 共模模式扼流线圈(直流、信号线路用)

回流焊

■型号标示法

※使用温度范围: -25～+105℃ (包含产品本身发热)

B U	0 5	M C	△ 0 1	△ T	△
①	②	③	④	⑤	⑥

△＝空格

①类型

代码	类型
BU	共模扼流线圈

②磁芯外径尺寸

代码	磁芯外径尺寸 [mm]
05	5.0

③外型

代码	外型
MC	表面贴装型

④试作代码

代码	试作代码
△01～△10	试作代码

⑤包装

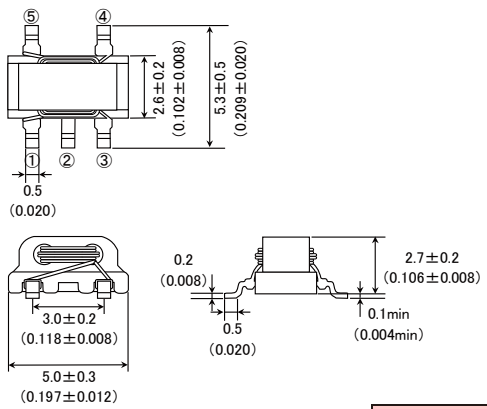
代码	包装
△T	卷盘带装

⑥本公司管理记号

代码	本公司管理记号
△	标准品

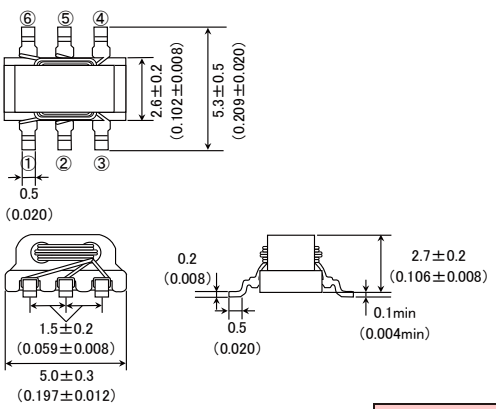
■标准外型尺寸 / 最小订货单位数量

BU05MC〔2 Lines〕type



Minimum quantity (pcs.) Embossed tape
2500

BU05MC〔3 Lines〕type



Minimum quantity (pcs.) Embossed tape
2500

单位: mm (inch)

未标记公差的数值仅供参考。

■型号一览

型号	EHS	匝数	阻抗值 [Ω] (typ.)	测试频率 [MHz]	直流电阻 [Ω] (max.)	额定电流 [A] (max.)	额定电压 [V] (D.C.)	绝缘阻抗 [MΩ] (min.)
BU05MC 01 T	RoHS	2	1000	60	0.12	1.0	50	100
BU05MC 08 T	RoHS	3	700	60	0.11	0.5	50	100

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SMD COMMON MODE CHOKE COILS FOR DC AND SIGNAL LINES, BALUN TRANSFORMERS

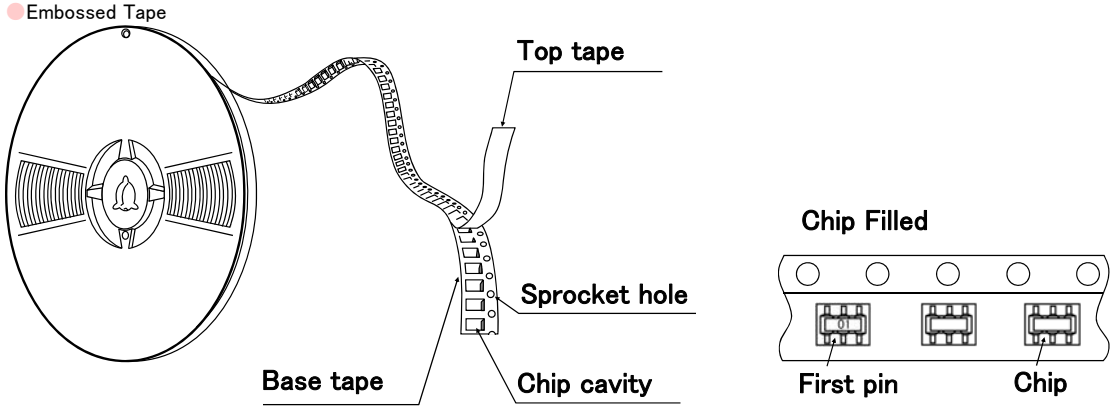
■PACKAGING

①Minimum Quantity

Type	Minimum Quantity [pcs]	
	Box	Taping
BU05MC	—	2500
BU06MB	150	—

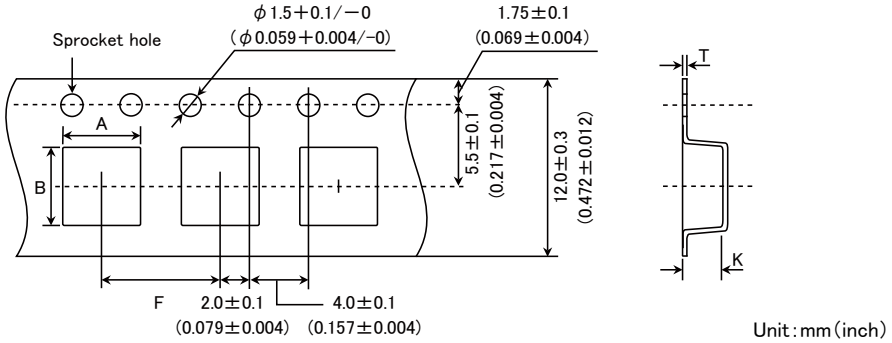
②Tape material

●Embossed Tape



③Taping dimensions

●Embossed tape 12mm wide (0.472 inches wide)

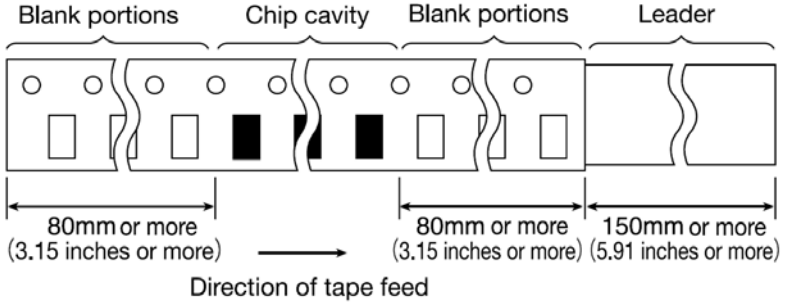


Unit:mm(inch)

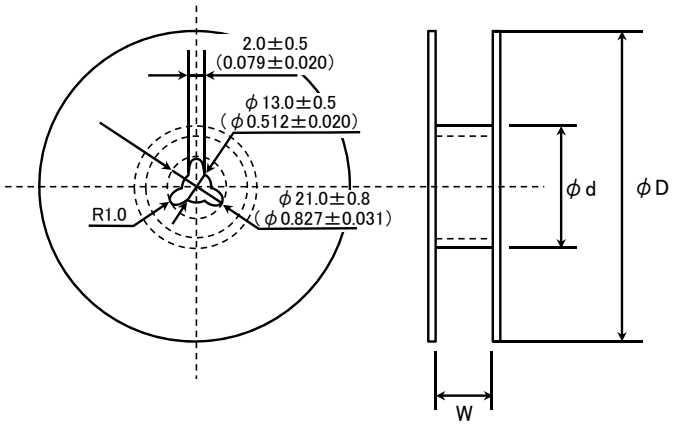
Type	Insertion pitch	Chip cavity		Tape thickness	
		A	B	K	T
BU05MC	8.0±0.1 (0.315±0.004)	5.2±0.1 (0.205±0.004)	5.6±0.1 (0.220±0.004)	3.2±0.1 (0.126±0.004)	0.4±0.05 (0.016±0.002)

Unit:mm(inch)

④Leader and Blank portion



⑤Reel size



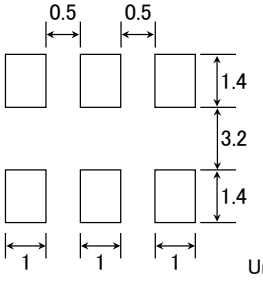
Type	φD	φd	W
BU05MC	330±2.0 (12.99±0.079)	80±1.0 (3.15±0.039)	13.5±1.0 (0.53±0.039)

Unit : mm (inch)

SMD COMMON MODE CHOKE COILS FOR DC AND SIGNAL LINES, BALUN TRANSFORMERS

■PRECAUTIONS

1. Circuit Design	
Precautions	◆Operating environment 1. The products described in this specification are intended for use in general electronic equipment, (office supply equipment, telecommunications systems, measuring equipment, and household equipment). They are not intended for use in mission-critical equipment or systems requiring special quality and high reliability (traffic systems, safety equipment, aerospace systems, nuclear control systems and medical equipment including life-support systems,) where product failure might result in loss of life, injury or damage. For such uses, contact TAIYO YUDEN Sales Department in advance.

2. PCB Design	
Precautions	◆Land pattern design 1. Please contact any of our offices for a land pattern, and refer to a recommended land pattern of specifications.
Technical considerations	◆Land pattern design Surface Mounting ・ Mounting and soldering conditions should be checked beforehand. ・ Applicable soldering process to these products is reflow soldering only. ・ Recommended Land Patterns 【BU05MC】  Unit:mm

3. Considerations for automatic placement	
Precautions	◆Adjustment of mounting machine 1. Excessive impact load should not be imposed on the products when mounting onto the PC boards. 2. Mounting and soldering conditions should be checked beforehand.
Technical considerations	◆Adjustment of mounting machine 1. When installing products, care should be taken not to apply distortion stress as it may deform the products.

4. Soldering	
Precautions	◆Reflow soldering 1. Please contact any of our offices for a reflow soldering, and refer to the recommended condition specified. 2. This product can be used reflow soldering only. 3. Please do not add any stress to a product until it returns in normal temperature after reflow soldering. ◆Lead free soldering 1. When using products with lead free soldering, we request to use them after confirming adhesion, temperature of resistance to soldering heat, soldering etc sufficiently. ◆Recommended conditions for using a soldering iron 【BU05MC】 ・ Put the soldering iron on the land-pattern. ・ Soldering iron's temperature – Below 350℃ ・ Duration – 3 seconds or less ・ The soldering iron should not directly touch the inductor.
Technical considerations	◆Reflow soldering 1. If products are used beyond the range of the recommended conditions, heat stresses may deform the products, and consequently degrade the reliability of the products. ◆Recommended conditions for using a soldering iron If products are used beyond the range of the recommended conditions, heat stresses may deform the products, and consequently degrade the reliability of the products.

5. Cleaning	
Precautions	◆Cleaning conditions 1. Please contact any of our offices for a cleaning.

6. Handling	
Precautions	◆Handling 1. Keep the product away from all magnets and magnetic objects. ◆Breakaway PC boards (splitting along perforations) 1. When splitting the PC board after mounting product, care should be taken not to give any stresses of deflection or twisting to the board. 2. Board separation should not be done manually, but by using the appropriate devices. ◆Mechanical considerations 1. Please do not give the product any excessive mechanical shocks. 2. Please do not add any shock and power to a product in transportation. ◆Pick-up pressure 1. Please do not push to add any pressure to a winding part. Please do not give any shock and push onto an exposed part of ferrite cores. ◆Packing 1. Please avoid accumulation of a packing box as much as possible.
Technical considerations	◆Handling 1. There is a case that a characteristic varies with magnetic influence. ◆Breakaway PC boards (splitting along perforations) 1. The position of the product on PCBs shall be carefully considered to minimize the stress caused from splitting of the PCBs. ◆Mechanical considerations 1. There is a case to be damaged by a mechanical shock. 2. There is a case to be broken by the handling in transportation. ◆Pick-up pressure 1. An excessive shock or stress may cause a damage to the product or a deterioration of a characteristic. ◆Packing 1. If packing boxes are accumulated, that could cause a deformation on packing tapes or a damage on the products.

7. Storage conditions	
Precautions	◆Storage 1. To maintain the solderability of terminal electrodes and to keep the packing material in good condition, temperature and humidity in the storage area should be controlled. ・ Recommended conditions Ambient temperature : 0～40℃, Humidity : Below 70% RH The ambient temperature must be kept below 30℃. Even under ideal storage conditions, the solderability of electrodes may decrease gradually. For this reason, the products should be used within one year from the time of delivery. In case of storage over 6 months, solderability shall be checked before actual usage.
Technical considerations	◆Storage 1. Under a high temperature and humidity environment, problems such as reduced solderability caused by oxidation of terminal electrodes and deterioration of taping/packaging materials may take place.

导线型共模模式扼流线圈(直流、信号线路用)

波峰焊

■型号标示法

※使用温度范围: -25～+105℃ (包含产品本身发热)

T L F	△ 9	U B H	3 0 2	W	K 1
①	②	③	④	⑤	⑥

△＝空格

①类型

代码	类型
TLF	共模扼流线圈

②磁芯外径尺寸

代码	磁芯外径尺寸 [mm]
△9	9

③外型

代码	外型
UB△	U 形磁芯、垂直分割绕线
UBH	U形磁芯、水平分割绕线

④标称电感值

代码 (例)	标称电感值 [μH]
302	3000
203	20000

⑤电感量公差

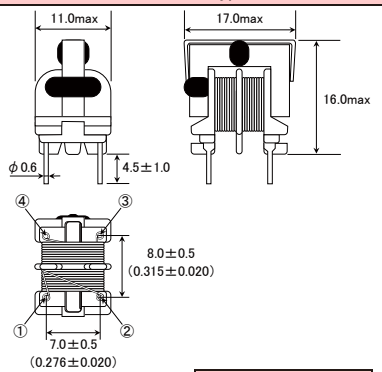
代码	电感量公差
W	＋100/－10%

⑥本公司管理记号

代码	本公司管理记号
K1	粘合固定

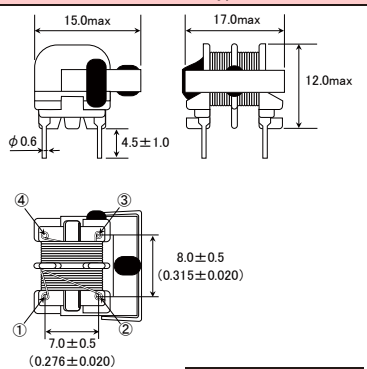
■标准外型尺寸 / 最小订货单位数量

TLF 9UB Type



Minimum quantity (pcs.)
Box
500

TLF 9UBH Type



Minimum quantity (pcs.)
Box
500

单位: mm (inch)

■型号一览

型号	EHS	匝数	电感值 [mH]	电感量公差	直流电阻 [Ω] (max.)	额定电流 [A] (max.)	额定电压 [V] (D.C.)	绝缘阻抗 [MΩ] (min.)
TLF 9UBH302W K1	RoHS	2	3.0	＋100/－10%	1.5	0.40	50	100
TLF 9UB 302W K1	RoHS	2	3.0	＋100/－10%	1.5	0.40	50	100
TLF 9UBH802W K1	RoHS	2	8.0	＋100/－10%	3.0	0.30	50	100
TLF 9UB 802W K1	RoHS	2	8.0	＋100/－10%	3.0	0.30	50	100
TLF 9UBH203W K1	RoHS	2	20.0	＋100/－10%	6.5	0.18	50	100
TLF 9UB 203W K1	RoHS	2	20.0	＋100/－10%	6.5	0.18	50	100

导线型共模模式扼流线圈(交流线路用)

波峰焊

■型号标示法

※使用温度范围: -25～+105℃ (包含产品本身发热)

T	L	F	△	9	U	A	△	1	0	2	△	0	R	8	K	1
①			②		③			④			⑤	⑥			⑦	

△=空格

①类型

代码	类型
TLF	共模模式扼流圈
TLH	混合阻风门

②磁芯尺寸

代码	磁芯尺寸 [mm]
△9	9
10	10

③外型

代码	外型
UA△	U 形磁芯、垂直型
UAH	U 形磁芯、水平型
UB△	U 形磁芯、垂直分割绕线型
CB△	□形磁芯、垂直分割绕线型
CBH	□形磁芯、水平分割绕线型
HB△	日形磁芯、垂直分割型
HBH	日形磁芯、水平分割型

④标称电感值

代码 (例)	标称电感值 [μH]
102	1000
103	10000

⑤电感量公差

代码	电感量公差
△	公称值以上
W	＋100/－10%

⑥额定电流

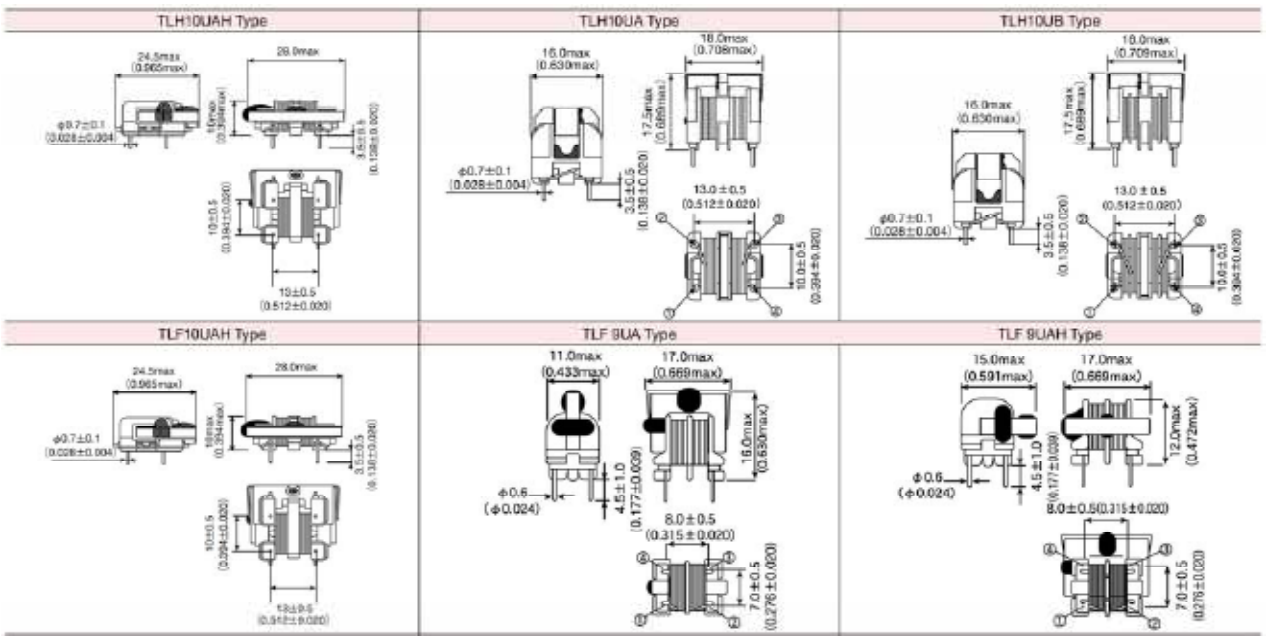
代码	额定电流 [A]
R54	0.54
0R8	0.8

※R=小数点

⑦本公司管理记号

代码	本公司管理记号
K1	标准品

■标准外型尺寸 / 最小订货单位数量



单位: mm (inch)

Type	Minimum quantity(pcs.) Box
TLH type	500
TLF type	

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■型号一览

●TLH10UAH 型（混成式扼流圈）

型号	EHS	共模模式 电感值 [mH]	电感值公差	正常模式 电感值 [mH]（typ.）	直流电阻 [Ω]（max.）	额定电流 [A]（max.）	额定电压AC [V]（max.）
TLH10UAH872 0R7	RoHS	8.7	min.	0.70	1.00	0.7	250
TLH10UAH992 0R6	RoHS	9.9	min.	0.85	1.35	0.6	250
TLH10UAH123 0R5	RoHS	12	min.	1.06	1.60	0.5	250

●TLH10UA 型（混成式扼流圈）

型号	EHS	共模模式 电感值 [mH]	电感值公差	正常模式 电感值 [mH]（typ.）	直流电阻 [Ω]（max.）	额定电流 [A]（max.）	额定电压AC [V]（max.）
TLH10UA 901 2R0	RoHS	0.9	min.	0.067	0.089	2.0	250
TLH10UA 112 1R8	RoHS	1.1	min.	0.087	0.126	1.8	250
TLH10UA 152 1R6	RoHS	1.5	min.	0.126	0.171	1.6	250
TLH10UA 212 1R4	RoHS	2.1	min.	0.160	0.222	1.4	250
TLH10UA 282 1R2	RoHS	2.8	min.	0.215	0.272	1.2	250
TLH10UA 432 1R0	RoHS	4.3	min.	0.330	0.398	1.0	250
TLH10UA 622 0R8	RoHS	6.2	min.	0.430	0.578	0.8	250
TLH10UA 872 0R7	RoHS	8.7	min.	0.644	0.878	0.7	250
TLH10UA 992 0R6	RoHS	9.9	min.	0.836	1.138	0.6	250
TLH10UA 143 0R5	RoHS	14	min.	1.256	1.567	0.5	250

●TLH10UB 型（混成式扼流圈）

型号	EHS	共模模式 电感值 [mH]	电感值公差	正常模式 电感值 [mH]（typ.）	直流电阻 [Ω]（max.）	额定电流 [A]（max.）	额定电压AC [V]（max.）
TLH10UB 701 2R0	RoHS	0.7	min.	0.056	0.097	2.0	250
TLH10UB 112 1R7	RoHS	1.1	min.	0.068	0.133	1.7	250
TLH10UB 142 1R4	RoHS	1.4	min.	0.113	0.214	1.4	250
TLH10UB 232 1R2	RoHS	2.3	min.	0.150	0.274	1.2	250
TLH10UB 352 1R0	RoHS	3.5	min.	0.232	0.422	1.0	250
TLH10UB 442 0R8	RoHS	4.4	min.	0.328	0.624	0.8	250
TLH10UB 872 0R7	RoHS	8.7	min.	0.580	0.982	0.7	250
TLH10UB 972 0R6	RoHS	9.7	min.	0.735	1.314	0.6	250
TLH10UB 113 0R5	RoHS	11	min.	0.877	1.577	0.5	250

●TLF10UAH 型

型号	EHS	共模模式 电感值 [mH]	电感值公差	直流电阻 [Ω]（max.）	额定电流 [A]（max.）	额定电压AC [V]（max.）
TLF10UAH872 0R7	RoHS	8.7	min.	1.00	0.7	250
TLF10UAH992 0R6	RoHS	9.9	min.	1.35	0.6	250
TLF10UAH123 0R5	RoHS	12	min.	1.60	0.5	250

●TLF 9UA 型

型号	EHS	共模模式 电感值 [mH]	电感值公差	直流电阻 [Ω]（max.）	额定电流 [A]（max.）	额定电压AC [V]（max.）
TLF 9UA 102W0R8K1	RoHS	1.0	＋100/－10%	0.5	0.80	250
TLF 9UA 202WR54K1	RoHS	2.0	＋100/－10%	1.0	0.54	250
TLF 9UA 302WR42K1	RoHS	3.0	＋100/－10%	1.5	0.42	250
TLF 9UA 502WR32K1	RoHS	5.0	＋100/－10%	2.5	0.32	250
TLF 9UA 802WR25K1	RoHS	8.0	＋100/－10%	4.0	0.25	250
TLF 9UA 103WR23K1	RoHS	10	＋100/－10%	4.5	0.23	250

●TLF 9UAH 型

型号	EHS	共模模式 电感值 [mH]	电感值公差	直流电阻 [Ω]（max.）	额定电流 [A]（max.）	额定电压AC [V]（max.）
TLF 9UAH102W0R8K1	RoHS	1.0	＋100/－10%	0.5	0.80	250
TLF 9UAH202WR54K1	RoHS	2.0	＋100/－10%	1.0	0.54	250
TLF 9UAH302WR42K1	RoHS	3.0	＋100/－10%	1.5	0.42	250
TLF 9UAH502WR32K1	RoHS	5.0	＋100/－10%	2.5	0.32	250
TLF 9UAH802WR25K1	RoHS	8.0	＋100/－10%	4.0	0.25	250
TLF 9UAH103WR23K1	RoHS	10	＋100/－10%	4.5	0.23	250

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LEADED COMMON MODE CHOKE COILS FOR DC AND SIGNAL LINES
LEADED COMMON MODE CHOKE COILS FOR AC LINES

■PACKAGING

①Minimum Quantity

●TLH/TLF Type

Type	Minimum Quantity[pcs]
	Box
TLH10UA□	1000
TLH10UB	
TLF10UAH	
TLF9UA□	500
TLF9UB□	

LEADED COMMON MODE CHOKE COILS FOR DC AND SIGNAL LINES, LEADED COMMON MODE CHOKE COILS FOR AC LINES

■RELIABILITY DATA

1. Operating Temperature Range		
Specified Value	TLH, TLF Type	−25～＋ 105℃
Test Method and Remarks	Including temperature rise due to self−generated heat.	

2. Storage temperature range		
Specified Value	TLH, TLF Type	−40～＋ 85℃

3. Rated current		
Specified Value	TLH, TLF Type	Within the specified range
Test Method and Remarks	TLH10U, TLF10UA : The maximum value of AC current within the temperature rise of 60℃ TLF9UA, : The maximum value of AC current within the temperature rise of 45℃ TLF9UB : The maximum value of DC current within the temperature rise of 45℃	

4. Inductance		
Specified Value	TLH, TLF Type	Within the specified tolerance
Test Method and Remarks	TLF9U : Measuring equipment : LCR meter 4284A or its equivalent Measuring frequency : 1kHz Measuring voltage : 1Vrms TLH、TLF(except TLF9U) : Measuring equipment : LCR meter 4284A or its equivalent Measuring frequency : 1kHz Measuring voltage : 0.1Vrms	

5. DC resistance		
Specified Value	TLH, TLF Type	Within the specified tolerance
Test Method and Remarks	Measuring equipment : DC ohmmeter	

6. Terminal strength tensile force		
Specified Value	TLH, TLF Type	No abnormality
Test Method and Remarks	TLH10UA, TLH10UB, TLF9U : Apply the stated tensile force gradually in the direction to draw terminal. force [N] / duration [s]: 5 / 30±5 TLH10UAH, TLF (except TLF9U): Apply the stated tensile force gradually in the direction to draw terminal. force [N] / duration [s]: 10 / 30±5	

7. Insulation resistance between wires		
Specified Value	TLH, TLF Type	100MΩmin.
Test Method and Remarks	Applied voltage : 500VDC (TLH, TLF (except TLF9UB)) : 250VDC (TLF9UB) Duration : 60sec.	

8. Insulation resistance between wire and core		
Specified Value	TLH, TLF Type	100MΩ min.(except TLH, TLF10UAH Type)
Test Method and Remarks	TLF : Applied voltage : 500VDC (TLF (except TLF9UB)) : 250VDC (TLF9UB) Duration : 60 sec.	

9. Withstanding : between wires		
Specified Value	TLH, TLF Type	No abnormality
Test Method and Remarks	Applied voltage : 2000VAC (TLH, TLF (except TLF9UB)) : 500VDC (TLF9UB) Duration : 60sec	

10. Withstanding : between wires and core		
Specified Value	TLH, TLF Type	No abnormality(except TLH, TLF10UAH Type)
Test Method and Remarks	TLF : Applied voltage : 2000VAC (TLF (except TLF9UB)) : 500VDC (TLF9UB) Duration : 60sec.	

11. Rated voltage		
Specified Value	TLH, TLF Type	Within the specified range
Test Method and Remarks	TLH, TLF (except TLF9UB) : 250VAC TLF9UB : 50VDC	

12. Resistance to vibration		
Specified Value	TLH, TLF Type	TLF9U : Inductance change : Within ±5% TLH, TLF (except TLF9U) : Appearance is no abnormality and within the specified range
Test Method and Remarks	TLH, TLF : According to JIS C60068-2-6. Direction : 2hrs each in X, Y and Z direction Total : 6hrs Frequency range : 10 to 55 to 10Hz (1 min.) Amplitude : 1.5mm (shall not exceed acceleration 196m/s^2) Mounting method : soldering onto PC board Recovery : At least 1hr of recovery under the standard condition after the removal from test chamber, followed by the measurement within 2hrs.	

13. Solderability		
Specified Value	TLH, TLF Type	At least 90% of terminal electrode is covered by new solder.
Test Method and Remarks	TLH, TLF : Solder temperature : 235±0.5℃ Duration : 2±0.5sec. Immersion depth : Up to 1.5 to 2.0mm from PBC mounted level. TLH, TLF : Solder temperature : 245±5℃ Duration : 4±1sec. Immersion depth : Up to 1.0 to 1.5mm from PBC mounted level.	

14. Resistance to soldering heat

Specified Value	TLH, TLF Type	TLF9UA : Inductance change : Within ±5%
Test Method and Remarks	TLH, TLF : Solder temperature : 260±5℃ Duration : 5±0.5sec. Immersion depth : Up to 1.5 to 2.0mm from PBC mounted level. Recovery : At least 1hr of recovery under the standard condition after the removal from test chamber, followed by the measurement within 2hrs. TLH, TLF : Solder temperature : 260±5℃ Duration : 10±1sec. Immersion depth : Up to 1.0 to 1.5mm from PBC mounted level. Recovery : At least 1hr of recovery under the standard condition after the removal from test chamber, followed by the measurement within 2hrs.	

15. Thermal shock

Specified Value	TLH, TLF Type	TLF9UA : Inductance change : Within ±15% TLH, TLF (except TLF9UA) : Withstanding voltage : No abnormality Insulation resistance : No abnormality
Test Method and Remarks	TLH, TLF : According to JIS C60068-2-14. Conditions for 1 cycle -25℃～+85℃、keep each 30min Number of cycles : 10 Recovery : At least 1hr of recovery under the standard condition after the removal from test chamber, followed by the measurement within 2 hrs.	

16. Damp heat

Specified Value	TLH, TLF Type	TLF9UA : Inductance change : Within ±15% TLH, TLF (except TLF9UA) : Withstanding voltage : No abnormality Insulation resistance : No abnormality
Test Method and Remarks	TLH, TLF : Temperature : 60±2℃ : 40±2℃ (※except TLF9U) Humidity : 90～95%RH Duration : 500 hrs Recovery : At least 1hr of recovery under the standard removal from test chamber followed by the measurement within 2 hrs.	

17. Loading under damp heat

Specified Value	TLH, TLF Type	Withstanding voltage : No abnormality Insulation resistance : No abnormality
Test Method and Remarks	TLH, TLF : Temperature : 60±2℃ : 40±2℃ (※except TLF9U) Humidity : 90～95%RH Duration : 100 hrs : 500 hrs Apply rated current across windings (※except TLF9U) Applied voltage : Apply the following specified voltage between windings. TLF9UA 250VAC TLF9UB 50VDC Recovery : At least 1hr of recovery under the standard removal from test chamber followed by the measurement within 2 hrs.	

18. Low temperature life test		
Specified Value	TLH, TLF Type	TLF9U : Inductance change : Within ±15% TLH, TLF (except TLF9U) : Withstanding voltage : No abnormality Insulation resistance : No abnormality
Test Method and Remarks	TLH, TLF : Temperature : −25±2℃ : −40±2℃ (※TLF・TLH) Duration : 500 hrs Recovery : At least 1hr of recovery under the standard removal from test chamber followed by the measurement within 2 hrs.	

19. High Temperature life test		
Specified Value	TLH, TLF Type	TLF9U : Inductance change : Within ±15% TLH, TLF (except TLF9U) : Withstanding voltage : No abnormality Insulation resistance : No abnormality
Test Method and Remarks	TLH, TL F : Temperature : 105±3℃ (※ TLF・TLH) Duration : 500 hrs Recovery : At least 1hr of recovery under the standard removal from test chamber followed by the measurement within 2 hrs.	

LEADED COMMON MODE CHOKE COILS FOR DC AND SIGNAL LINES, LEADED COMMON MODE CHOKE COILS FOR AC LINES

■PRECAUTIONS

1. Circuit Design	
Precautions	◆Operating environment 1. The products described in this specification are intended for use in general electronic equipment, (office supply equipment, telecommunications systems, measuring equipment, and household equipment). They are not intended for use in mission-critical equipment or systems requiring special quality and high reliability (traffic systems, safety equipment, aerospace systems, nuclear control systems and medical equipment including life-support systems) where product failure might result in loss of life, injury or damage. For such uses, contact TAIYO YUDEN Sales Department in advance.

2. PCB Design	
Precautions	◆Design 1. Please design insertion pitches as matching to that of leads of the component on PCBs.
Technical considerations	◆Design 1. When Inductors are mounted onto a PC board, hole dimensions on the board should match the lead pitch of the component, if not, it will cause breakage of the terminals or cracking of terminal roots covered with resin as excess stress travels through the terminal legs.

3. Soldering	
Precautions	◆Wave soldering 1. Please refer to the specifications in the catalog for a wave soldering. 2. Do not immerse the entire inductor in the flux during the soldering operation. ◆Lead free soldering 1. When using products with lead free soldering, we request to use them after confirming of adhesion, temperature of resistance to soldering heat, etc. sufficiently. ◆Recommended conditions for using a soldering iron ・ Put the soldering iron on the land-pattern. ・ Soldering iron's temperature – Below 350°C ・ Duration – 3 seconds or less ・ The soldering iron should not directly touch the product.
Technical considerations	◆Lead free soldering 1. If products are used beyond the range of the recommended conditions, heat stresses may deform the products, and consequently degrade the reliability of the products. ◆Recommended conditions for using a soldering iron If products are used beyond the range of the recommended conditions, heat stresses may deform the products, and consequently degrade the reliability of the products.

4. Cleaning	
Precautions	◆Cleaning conditions 1. TLF type Please contact any of our offices for about a cleaning.

5. Handling	
Precautions	◆Handling 1. Keep the product away from all magnets and magnetic objects. ◆Mechanical considerations 1. Please do not give the product any excessive mechanical shocks. 2. TLF type Please do not add any shock or power to a product in transportation. ◆Packing 1. Please do not give the product any excessive mechanical shocks. In loading, please pay attention to handling indication mentioned in a packing box (a loading direction / number of maximum loading / fragile item).
Technical considerations	◆Handling 1. There is a case that a characteristic varies with magnetic influence. ◆Mechanical considerations 1. There is a case to be damaged by a mechanical shock. 2. TLF type There is a case to be broken by a fall. ◆Packing 1. There is a case that a lead route turns at by a fall or an excessive shock.

6. Storage conditions	
Precautions	◆Storage 1. To maintain the solderability of terminal electrodes and to keep the packing material in good condition, temperature and humidity in the storage area should be controlled. ・ Recommended conditions Ambient temperature : 0～40℃ Humidity : Below 70% RH The ambient temperature must be kept below 30℃. Even under ideal storage conditions, the solderbility of electrodes decreases gradually, so the products should be mounted within one year from the time of delivery. In case of storage over 6 months, solderability shall be checked before actual usage.
Technical considerations	◆Storage 1. Under a high temperature and humidity environment, problems such as reduced solderability caused by oxidation of terminal electrodes and deterioration of taping/packaging materials may take place.